



NT1193FAAE2S

GNSS Wideband Low Noise Amplifier

FEATURES

- Frequency range: 1164 MHz to 1610 MHz
- Supply voltage: 1.5 V to 3.7 V (2.8 V typ.)
- Low current: 5 mA typ.
- High gain: 21.5 dB typ.@ L1/2/5/6 band
- Low NF: 0.7 dB typ.@ L1/2/5/6 band
- P-1dB(IN): -16 dBm typ.@ L1/2/5/6 band
- With stand-by function
- Small package size: 0.7 x 1.1 mm typ.
t = 0.39 mm max.
- Operating temperature range: -40 to +105°C
- RoHS compliant and Halogen Free, MSL1

GENERAL DESCRIPTION

The NT1193 is a GNSS wideband low noise amplifier (LNA) designed for multi-band GNSS systems.

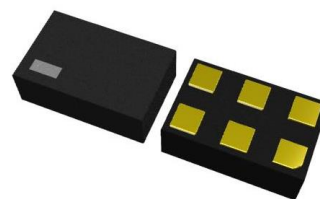
This LNA features high gain and low noise figure in all GNSS band from L1 to L2/L5/L6, which makes it ideal for GNSS module and IoT device applications. The stand-by function contributes to reduce current consumption.

This LNA features wide operating temperature range from -40 to +105°C.

This LNA achieves compact mounting area by small size package EPFFP-6-FA and only two external components.

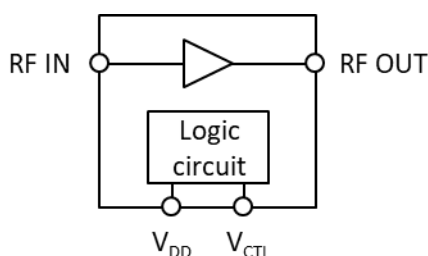
APPLICATIONS

- GNSS (GPS, GLONASS, Galileo, BeiDou, etc.) receiver applications
- GNSS modules
- Tracking devices
- Drone



EPFFP-6-FA
0.7 × 1.1 × 0.39 (mm)

BLOCK DIAGRAM



■ PRODUCT NAME INFORMATION

NT1193 FA A E2 S

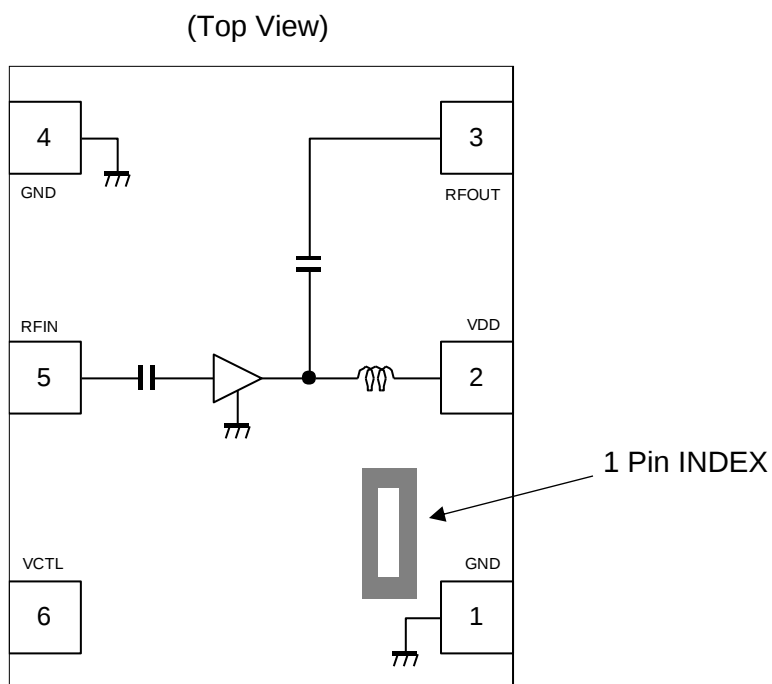
Description of configuration

Suffix	Parameter	Description
FA	Package code	Indicates the package. Refer to the order information.
A	Version	Indicates the product version. "A" is initial version.
E2	Packing	Refer to the packing specifications.
S	Grade	Indicates the quality grade. "S" means general-purpose and consumer application. Operating temperature range: -40°C to 105°C, Test temperature: 25°C

■ ORDER INFORMATION

PRODUCT NAME	PACKAGE	RoHS	HALOGEN-FREE	PLATING COMPOSITION	WEIGHT (mg)	QUANTITY PER REEL (pcs/reel)
NT1193FAAE2S	EPFFP-6-FA	Yes	Yes	Au	0.7	5000

■ PIN DESCRIPTIONS



EPFFP-6-FA Pin Configuration

Pin No.	Pin Name	Description
1	GND	Ground terminal
2	VDD	Operating voltage supply terminal
3	RFOUT	RF output terminal
4	GND	Ground terminal
5	RFIN	RF input terminal
6	VCTL	Control signal input terminal

Please refer to "[APPLICATION CIRCUIT](#)" for details.

■ TRUTH TABLE

"H"= $V_{CTL}(H)$, "L"= $V_{CTL}(L)$

V_{CTL}	Mode
H	Active mode
L	Stand-by mode

■ ABSOLUTE MAXIMUM RATINGS

General conditions: $T_a = +25^{\circ}\text{C}$, $Z_s = Z_l = 50\Omega$

	Symbol	Ratings	Unit
Supply voltage	V_{DD}	5.0	V
Control voltage	V_{CTL}	5.0	V
Input power	P_{IN}^{*1}	+18	dBm
Power dissipation	P_D^{*2}	430	mW
Operating temperature range	T_{opr}	-40 to +105	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	-55 to +150	$^{\circ}\text{C}$

*1 $V_{DD} = 2.8\text{ V}$ *2 4-layer FR4 PCB with through-hole (101.5 x 114.5 mm), $T_j = 150^{\circ}\text{C}$

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the lifetime and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

*1 Calculate the power consumption of the IC from the operating conditions and calculate the junction temperature with the thermal resistance.

Please refer to "[THERMAL CHARACTERISTICS](#)" for the thermal resistance under our measurement board conditions.

■ THERMAL CHARACTERISTICS

Parameter	Measurement Result
Thermal Resistance (θ_{ja})	$\theta_{ja} = 290.7^{\circ}\text{C/W}$

θ_{ja} : Junction-to-Ambient Thermal Resistance

■ ELECTROSTATIC DISCHARGE RATINGS

	Conditions	Pin No.	Pin Name	Protection Voltage	
				Ground	VDD
HBM	$C = 100\text{ pF}$, $R = 1.5\text{ k}\Omega$	1	GND	COM.	$\pm 125\text{ V}$
		2	VDD	$\pm 2000\text{ V}$	COM.
		3	RFOUT	$\pm 2000\text{ V}$	$\pm 2000\text{ V}$
		4	GND	COM.	$\pm 2000\text{ V}$
		5	RFIN	$\pm 2000\text{ V}$	$\pm 2000\text{ V}$
		6	VCTL	$\pm 2000\text{ V}$	$\pm 500\text{ V}$

	Conditions	Protection Voltage
CDM	Field Induced CDM	$\pm 1000\text{ V}$

ELECTROSTATIC DISCHARGE RATINGS

The electrostatic discharge tests are done based on JEDEC JS-001 and JS-002.
In the HBM method, ESD is applied using the power supply pin and GND pin as reference pins.

■ RECOMMENDED OPERATING CONDITIONS

	Symbol	Value	Unit
Supply voltage	V_{DD}	1.5 to 3.7	V
Control voltage	V_{CTL}	1.5 to 3.7	V
Operating temperature range	T_a	-40 to +105	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

■ ELECTRICAL CHARACTERISTICS 1 (DC)

General conditions: $T_a = +25^{\circ}\text{C}$, $Z_s = Z_l = 50\Omega$

Parameter	Symbol	Conditions	MIN	TYP	MAX	Unit
Supply voltage	V_{DD}		1.5	2.8	3.7	V
Control voltage (High)	$V_{CTL(H)}$		1.5	1.8	3.7	V
Control voltage (Low)	$V_{CTL(L)}$		0	0	0.3	V
Operating current	I_{DD}	RF OFF, $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$	-	5	8	mA
		RF OFF, $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$	-	4.4	7	mA
		RF OFF, $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 0\text{ V}$	-	0.1	3	μA
		RF OFF, $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 0\text{ V}$	-	0.1	3	μA
Control current	I_{CTL}	RF OFF, $V_{CTL} = 1.8\text{ V}$	-	5	20	μA

■ ELECTRICAL CHARACTERISTICS 2 (RF)

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1164\text{ MHz to }1610\text{ MHz}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit

Parameter	Symbol	Conditions	MIN	TYP	MAX	Unit
Small signal gain	Gain	f = 1176 MHz (L5 band), Exclude PCB, connector loss (0.16 dB)	18	21.5	-	dB
		f = 1227 MHz (L2 band), Exclude PCB, connector loss (0.16 dB)				
		f = 1278 MHz (L6 band), Exclude PCB, connector loss (0.17 dB)				
		f = 1575 MHz (L1 band), Exclude PCB, connector loss (0.21 dB)				
Noise figure	NF	f = 1176 MHz (L5 band), Exclude PCB, connector loss (0.07 dB)	-	0.7	1.0	dB
		f = 1227 MHz (L2 band), Exclude PCB, connector loss (0.07 dB)				
		f = 1278 MHz (L6 band), Exclude PCB, connector loss (0.07 dB)				
		f = 1575 MHz (L1 band), Exclude PCB, connector loss (0.09 dB)				
Isolation	ISL	f = 1176 MHz (L5 band)	30	33	-	dB
		f = 1227 MHz (L2 band)				
		f = 1278 MHz (L6 band)				
		f = 1575 MHz (L1 band)				
Input power at 1 dB gain compression point	P-1dB(IN)	f = 1176 MHz (L5 band)	-21	-16	-	dBm
		f = 1227 MHz (L2 band)				
		f = 1278 MHz (L6 band)				
		f = 1575 MHz (L1 band)				
Input 3rd order intercept point	IIP3	f ₁ = 1176 MHz, f ₂ = f ₁ + 1 MHz, P _{IN} = -30 dBm	-11	-5	-	dBm
		f ₁ = 1227 MHz, f ₂ = f ₁ + 1 MHz, P _{IN} = -30 dBm				
		f ₁ = 1278 MHz, f ₂ = f ₁ + 1 MHz, P _{IN} = -30 dBm				
		f ₁ = 1575 MHz, f ₂ = f ₁ + 1 MHz, P _{IN} = -30 dBm				
Out of band input power at 1 dB gain compression point	P-1dB(IN)_OB	f _{jam} = 1850 MHz, f _{RF} = 1176 MHz at P _{IN} = -30 dBm	-23	-17	-	dBm
		f _{jam} = 1850 MHz, f _{RF} = 1227 MHz at P _{IN} = -30 dBm				
		f _{jam} = 1850 MHz, f _{RF} = 1278 MHz at P _{IN} = -30 dBm				
		f _{jam} = 1850 MHz, f _{RF} = 1575 MHz at P _{IN} = -30 dBm				
Out of band input 3rd order intercept point	IIP3_OB	f ₁ = 1785 MHz, f ₂ = 2401 MHz, P _{IN} = -20 dBm, f _{meas} = 1169 MHz	-13	-8	-	dBm
		f ₁ = 1713 MHz, f ₂ = 1850 MHz, P _{IN} = -20 dBm, f _{meas} = 1576 MHz				
RFIN Return loss	RLi	f = 1176 MHz (L5 band)	9	13	-	dB
		f = 1227 MHz (L2 band)				
		f = 1278 MHz (L6 band)				
		f = 1575 MHz (L1 band)				
RFOUT Return loss	RLo	f = 1176 MHz (L5 band)	10	16	-	dB
		f = 1227 MHz (L2 band)				
		f = 1278 MHz (L6 band)				
		f = 1575 MHz (L1 band)				
k factor	k	f = 50 MHz to 10 GHz	1	-	-	-

■ ELECTRICAL CHARACTERISTICS 3 (RF)

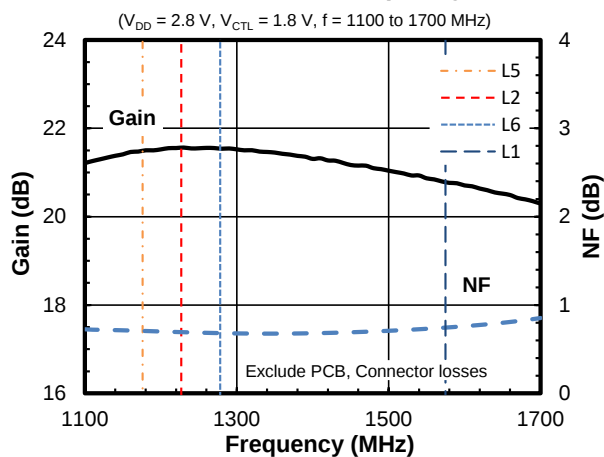
General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1164\text{ MHz}$ to 1610 MHz , $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit

Parameter	Symbol	Conditions	MIN	TYP	MAX	Unit
Small signal gain	Gain	$f = 1176\text{ MHz}$ (L5 band), Exclude PCB, connector loss (0.16 dB)	17	21	-	dB
		$f = 1227\text{ MHz}$ (L2 band), Exclude PCB, connector loss (0.16 dB)				
		$f = 1278\text{ MHz}$ (L6 band), Exclude PCB, connector loss (0.17 dB)				
		$f = 1575\text{ MHz}$ (L1 band), Exclude PCB, connector loss (0.21 dB)				
Noise figure	NF	$f = 1176\text{ MHz}$ (L5 band), Exclude PCB, connector loss (0.07 dB)	-	0.75	1.1	dB
		$f = 1227\text{ MHz}$ (L2 band), Exclude PCB, connector loss (0.07 dB)				
		$f = 1278\text{ MHz}$ (L6 band), Exclude PCB, connector loss (0.07 dB)				
		$f = 1575\text{ MHz}$ (L1 band), Exclude PCB, connector loss (0.09 dB)				
Isolation	ISL	$f = 1176\text{ MHz}$ (L5 band)	29	32	-	dB
		$f = 1227\text{ MHz}$ (L2 band)				
		$f = 1278\text{ MHz}$ (L6 band)				
		$f = 1575\text{ MHz}$ (L1 band)				
Input power at 1 dB gain compression point	P-1dB(IN)	$f = 1176\text{ MHz}$ (L5 band)	-25	-19	-	dBm
		$f = 1227\text{ MHz}$ (L2 band)				
		$f = 1278\text{ MHz}$ (L6 band)				
		$f = 1575\text{ MHz}$ (L1 band)				
Input 3rd order intercept point	IIP3	$f_1 = 1176\text{ MHz}$, $f_2 = f_1 + 1\text{ MHz}$, $P_{IN} = -30\text{ dBm}$	-14	-8	-	dBm
		$f_1 = 1227\text{ MHz}$, $f_2 = f_1 + 1\text{ MHz}$, $P_{IN} = -30\text{ dBm}$				
		$f_1 = 1278\text{ MHz}$, $f_2 = f_1 + 1\text{ MHz}$, $P_{IN} = -30\text{ dBm}$				
		$f_1 = 1575\text{ MHz}$, $f_2 = f_1 + 1\text{ MHz}$, $P_{IN} = -30\text{ dBm}$				
Out of band input power at 1 dB gain compression point	P-1dB(IN)_OB	$f_{jam} = 1850\text{ MHz}$, $f_{RF} = 1176\text{ MHz}$ at $P_{IN} = -30\text{ dBm}$	-27	-21	-	dBm
		$f_{jam} = 1850\text{ MHz}$, $f_{RF} = 1227\text{ MHz}$ at $P_{IN} = -30\text{ dBm}$				
		$f_{jam} = 1850\text{ MHz}$, $f_{RF} = 1278\text{ MHz}$ at $P_{IN} = -30\text{ dBm}$				
		$f_{jam} = 1850\text{ MHz}$, $f_{RF} = 1575\text{ MHz}$ at $P_{IN} = -30\text{ dBm}$				
Out of band input 3rd order intercept point	IIP3_OB	$f_1 = 1785\text{ MHz}$, $f_2 = 2401\text{ MHz}$, $P_{IN} = -20\text{ dBm}$, $f_{meas} = 1169\text{ MHz}$	-15	-10	-	dBm
		$f_1 = 1713\text{ MHz}$, $f_2 = 1850\text{ MHz}$, $P_{IN} = -20\text{ dBm}$, $f_{meas} = 1576\text{ MHz}$				
RFIN Return loss	RLi	$f = 1176\text{ MHz}$ (L5 band)	9	13	-	dB
		$f = 1227\text{ MHz}$ (L2 band)				
		$f = 1278\text{ MHz}$ (L6 band)				
		$f = 1575\text{ MHz}$ (L1 band)				
RFOUT Return loss	RLo	$f = 1176\text{ MHz}$ (L5 band)	10	18	-	dB
		$f = 1227\text{ MHz}$ (L2 band)				
		$f = 1278\text{ MHz}$ (L6 band)				
		$f = 1575\text{ MHz}$ (L1 band)				
k factor	k	$f = 50\text{ MHz}$ to 10 GHz	1	-	-	-

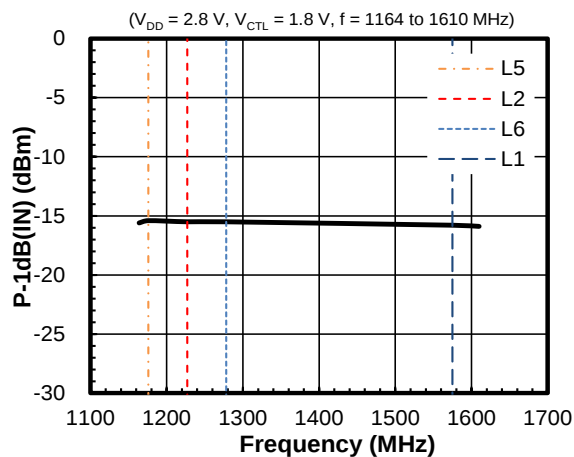
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

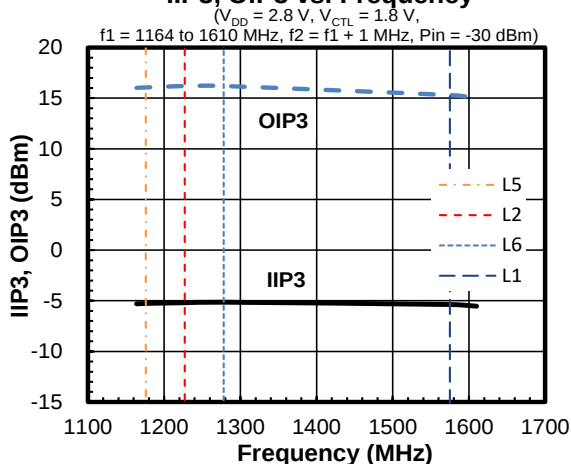
Gain, NF vs. Frequency



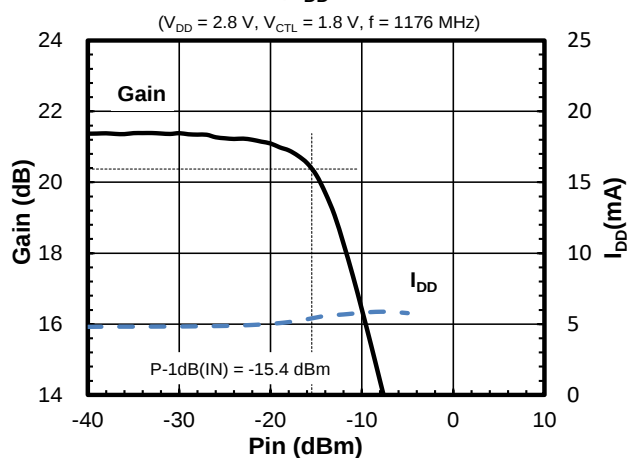
P-1dB(IN) vs. Frequency



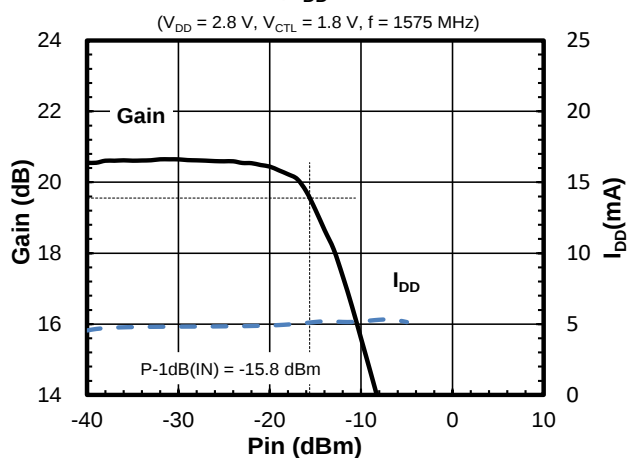
IIP3, OIP3 vs. Frequency



Gain, I_{DD} vs. Pin



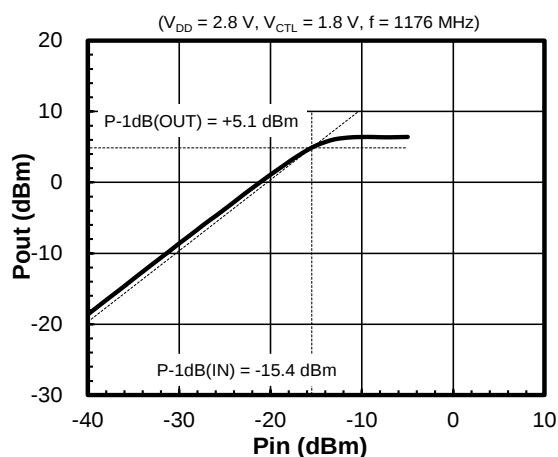
Gain, I_{DD} vs. Pin



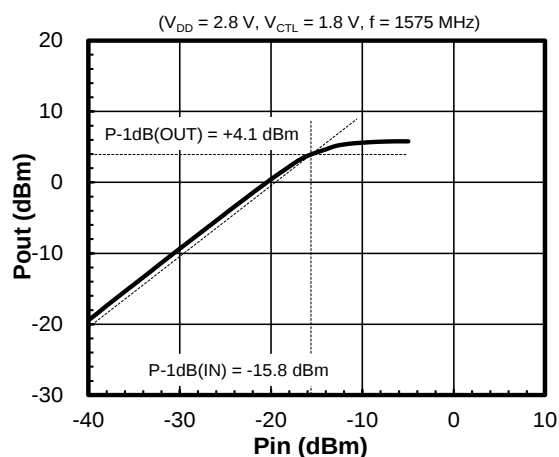
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

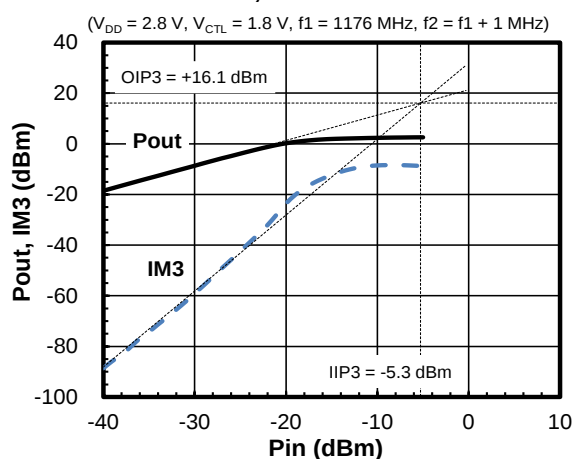
Pout vs. Pin



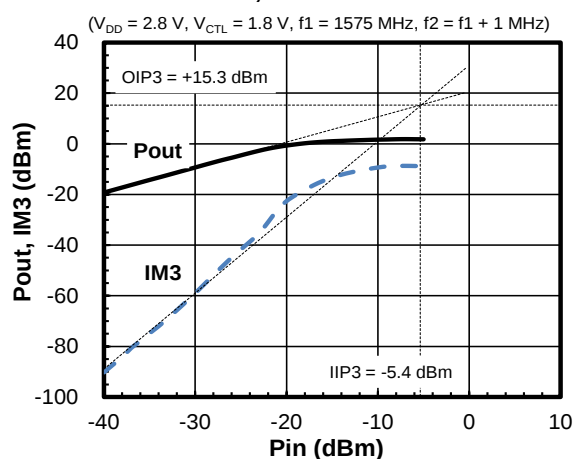
Pout vs. Pin



Pout, IM3 vs. Pin



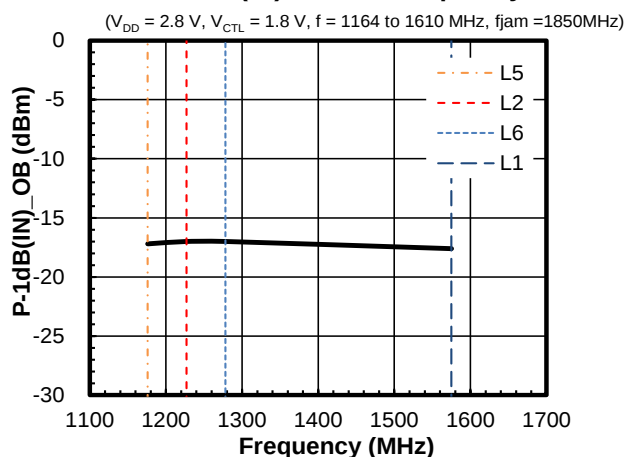
Pout, IM3 vs. Pin



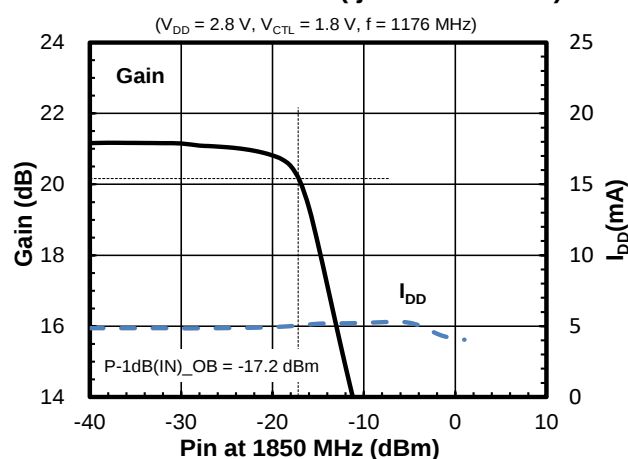
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

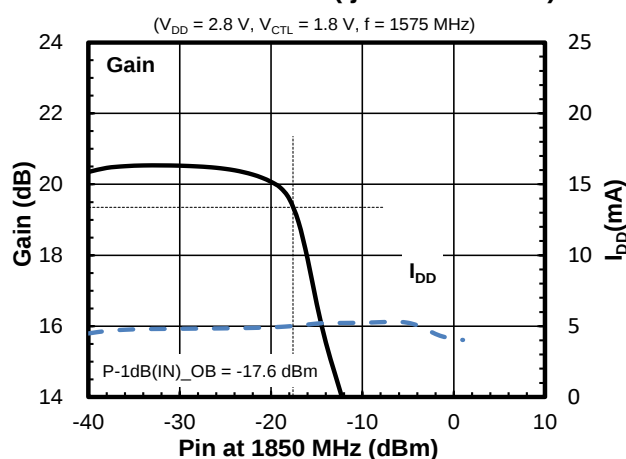
P-1dB(IN)_OB vs. Frequency



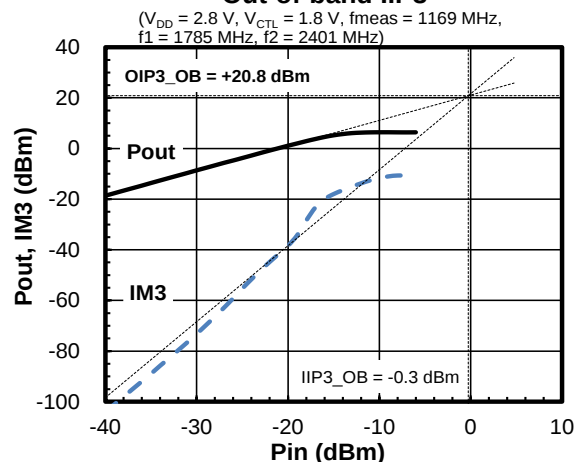
Out-of-band P-1dB ($f_{jam} = 1850\text{ MHz}$)



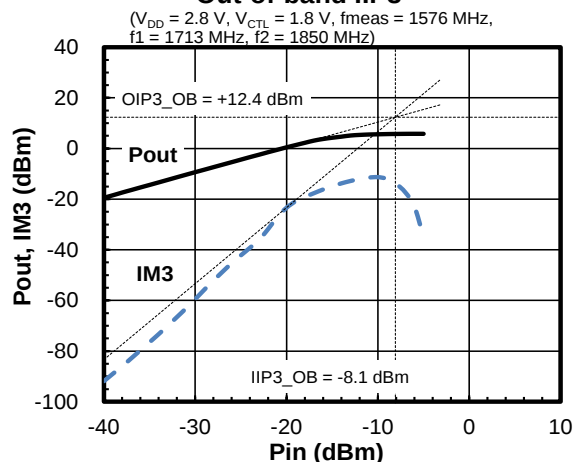
Out-of-band P-1dB ($f_{jam} = 1850\text{ MHz}$)



Out-of-band IIP3



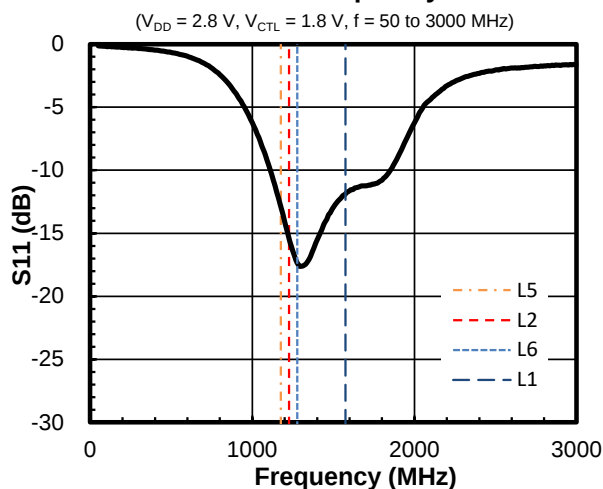
Out-of-band IIP3



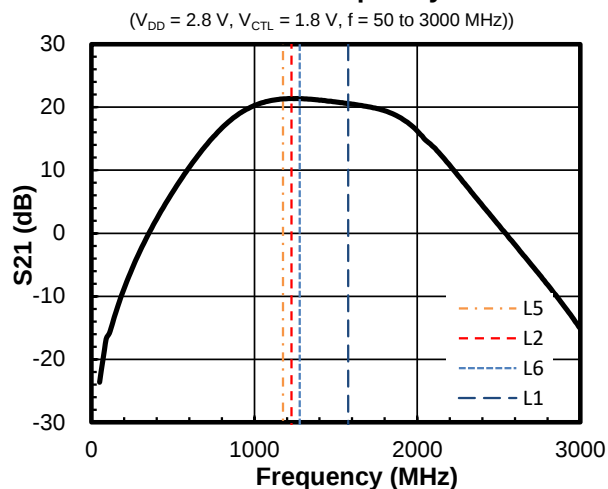
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

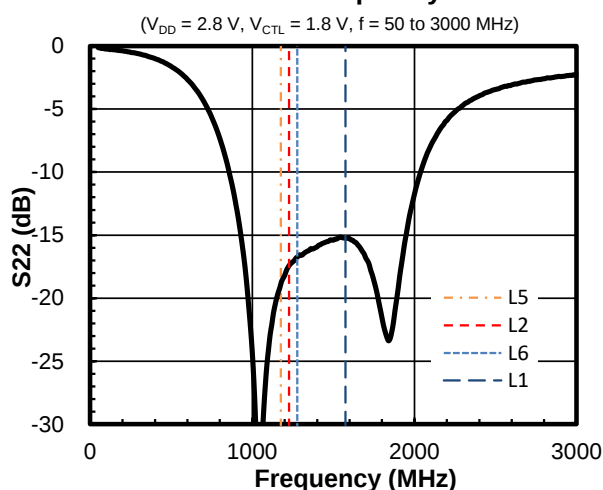
S11 vs. Frequency



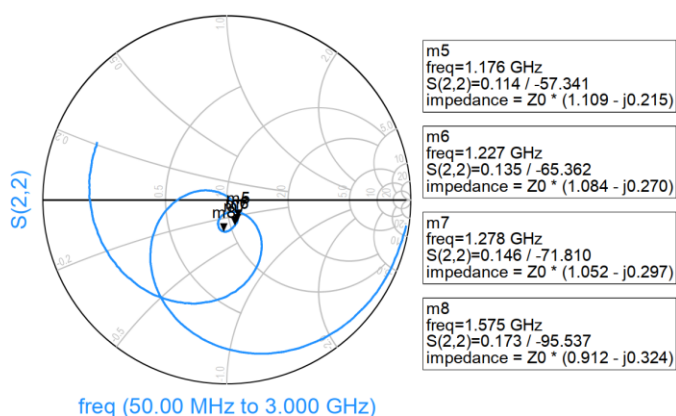
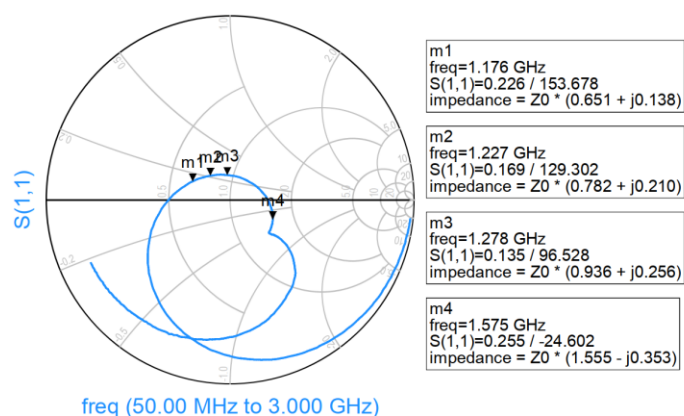
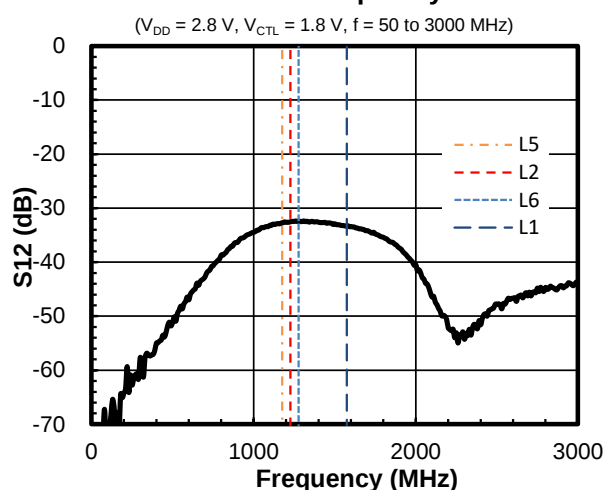
S21 vs. Frequency



S22 vs. Frequency



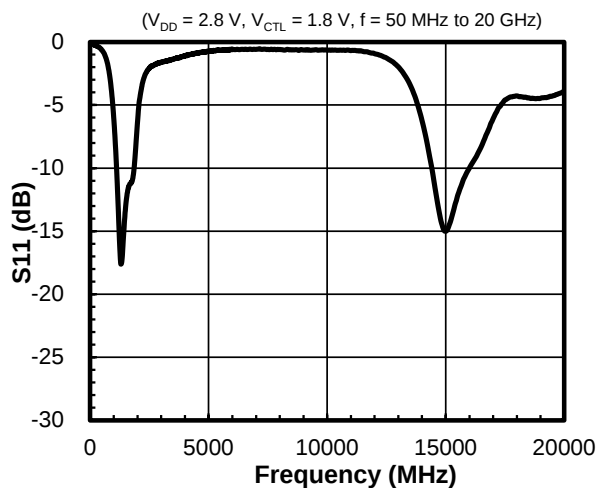
S12 vs. Frequency



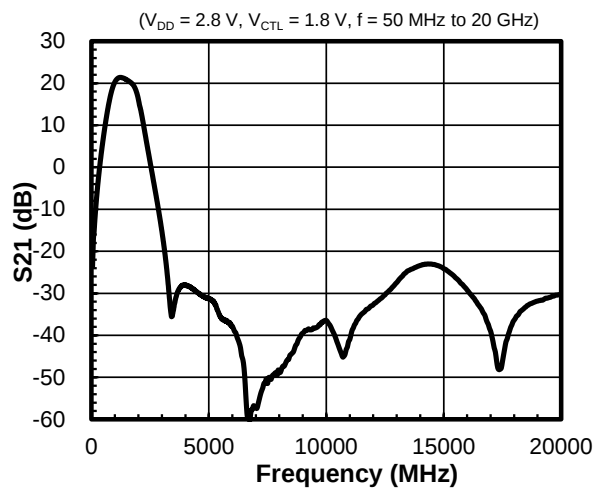
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

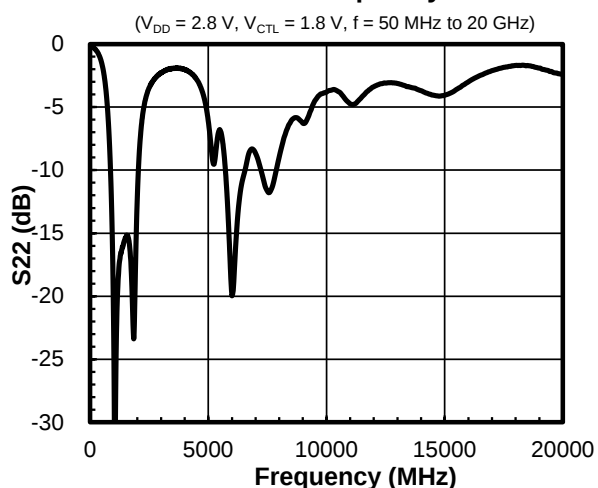
S11 vs. Frequency



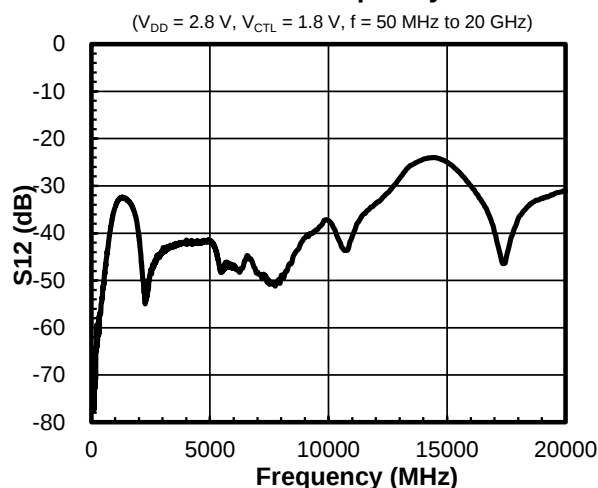
S21 vs. Frequency



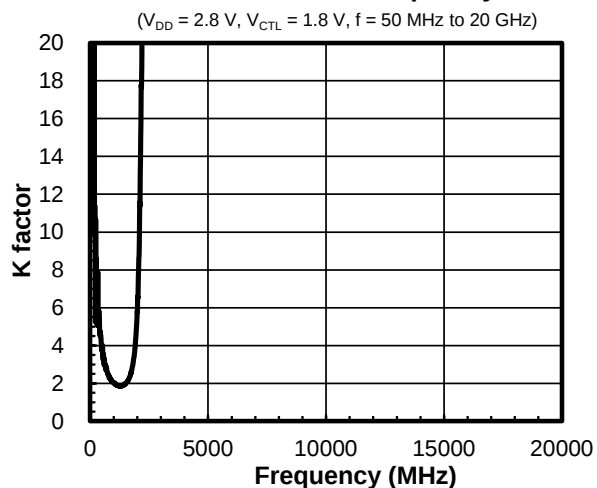
S22 vs. Frequency



S12 vs. Frequency

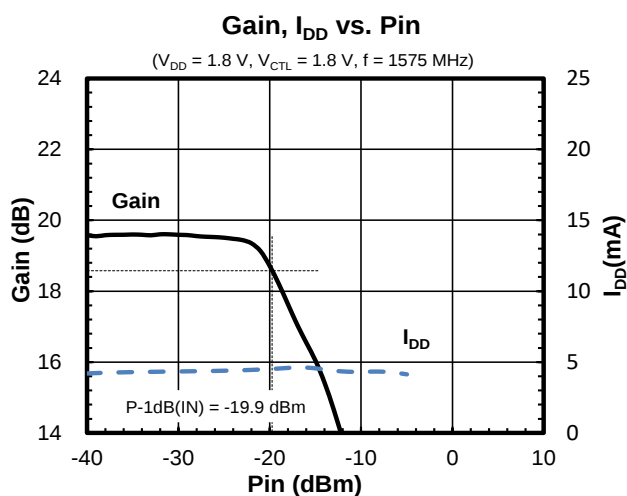
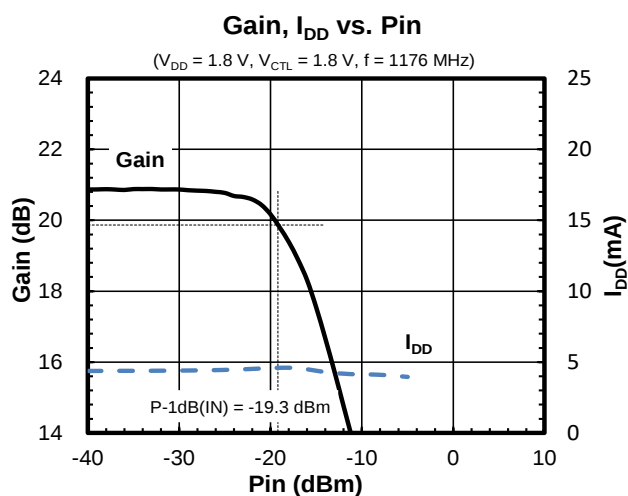
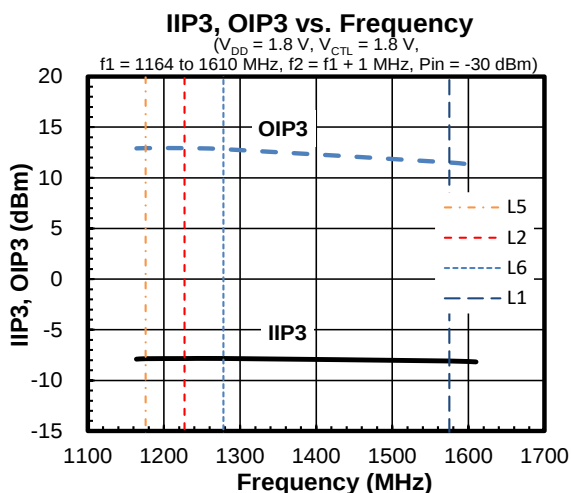
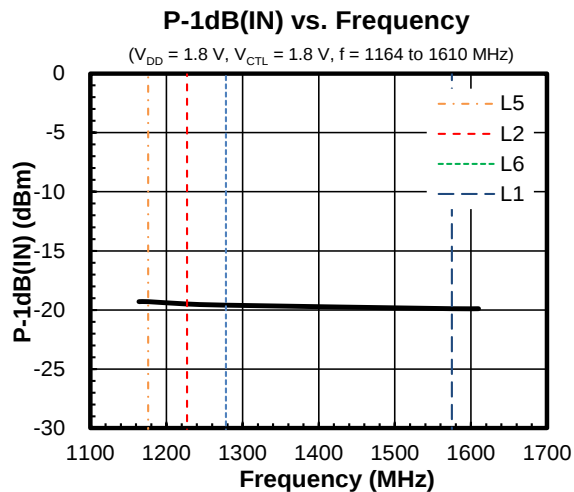
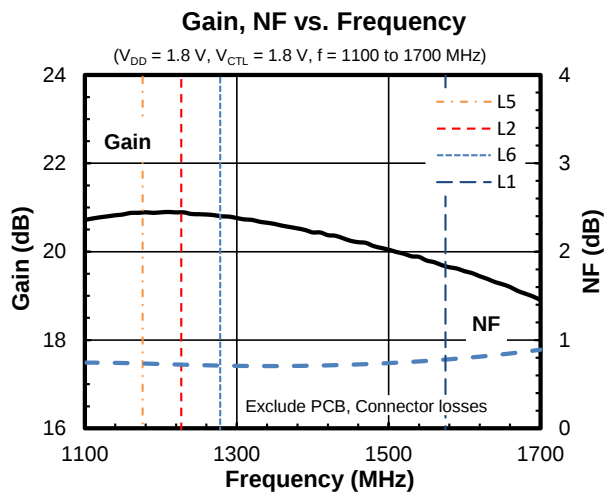


K factor vs. Frequency



■ TYPICAL CHARACTERISTICS

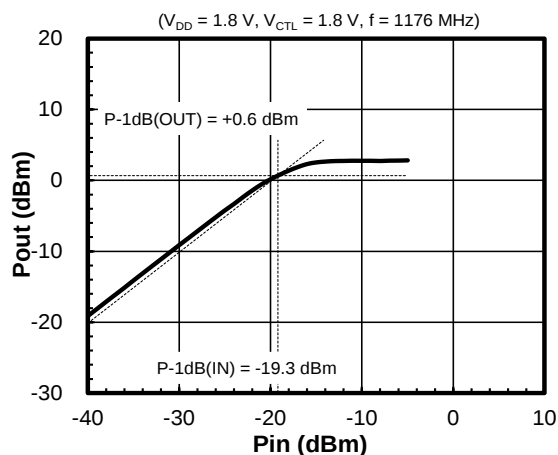
General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)



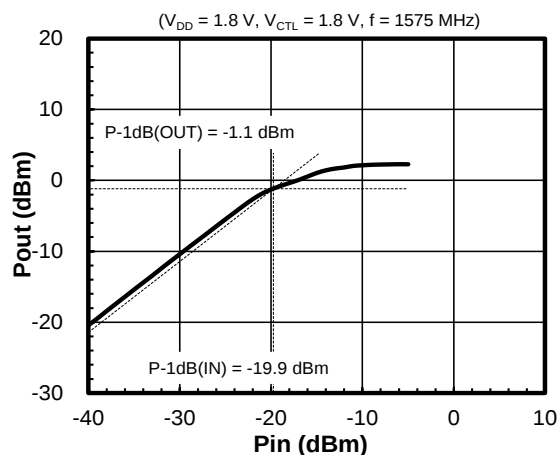
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

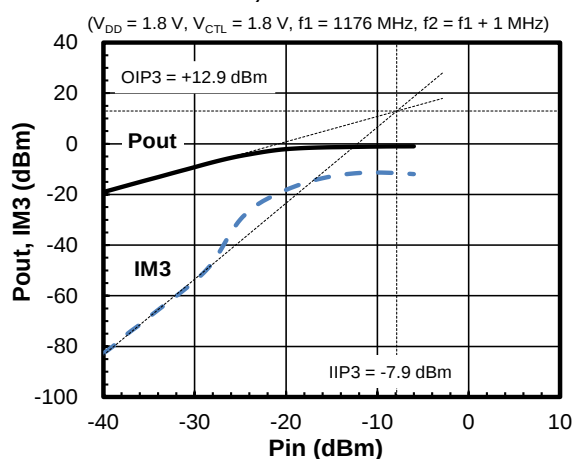
Pout vs. Pin



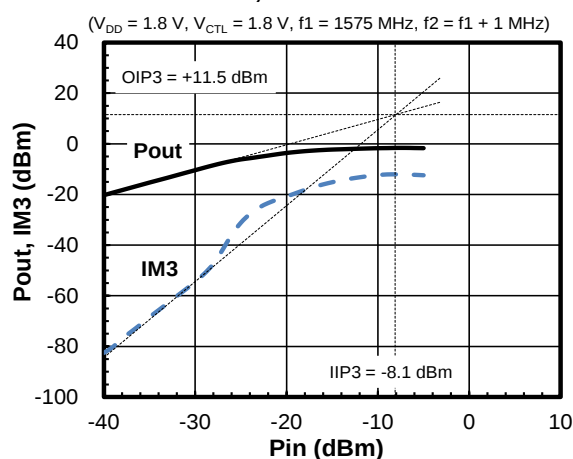
Pout vs. Pin



Pout, IM3 vs. Pin



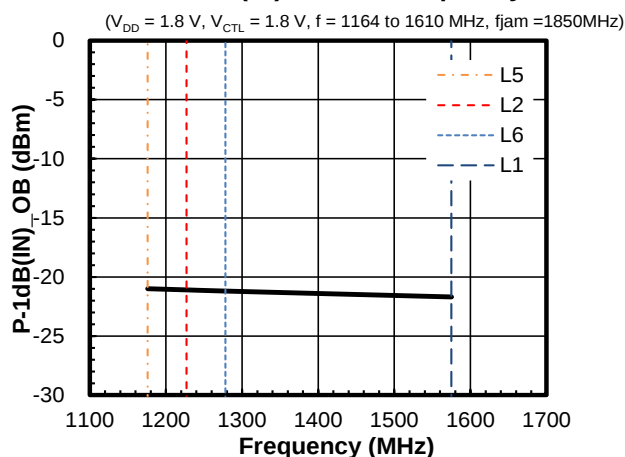
Pout, IM3 vs. Pin



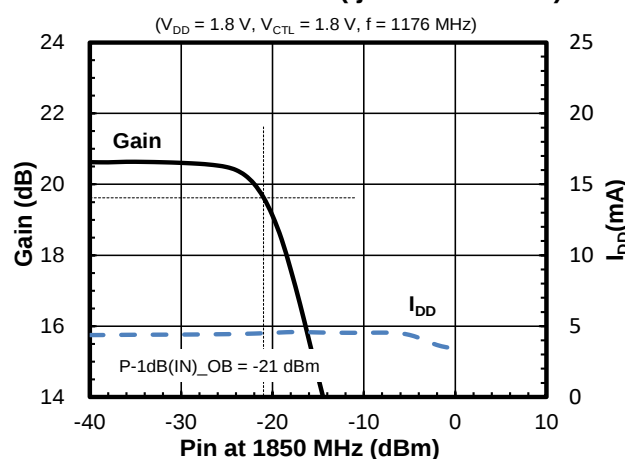
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

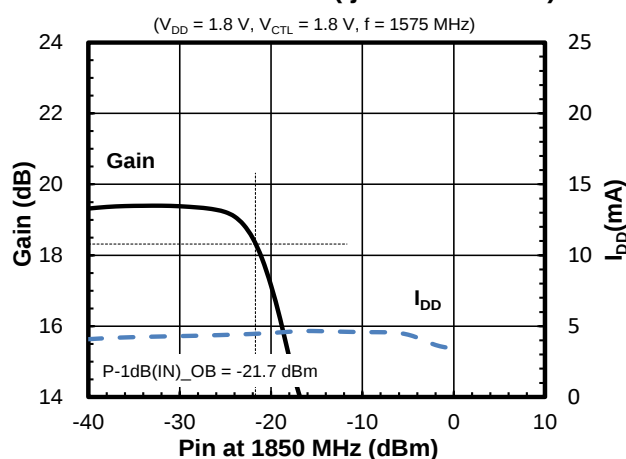
P-1dB(IN)_OB vs. Frequency



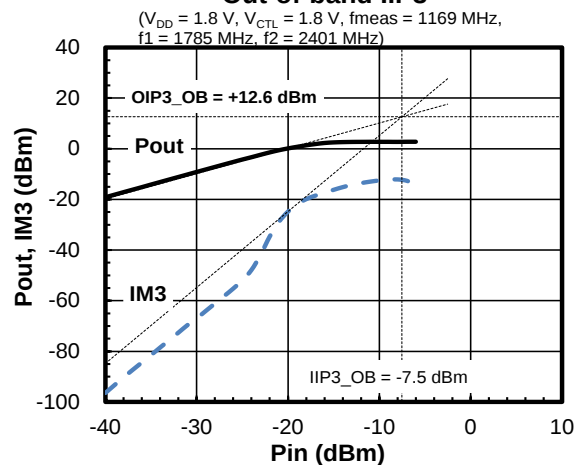
Out-of-band P-1dB ($f_{jam} = 1850\text{ MHz}$)



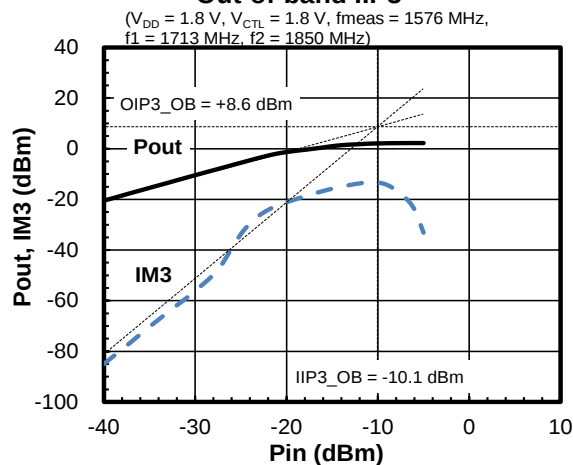
Out-of-band P-1dB ($f_{jam} = 1850\text{ MHz}$)



Out-of-band IIP3



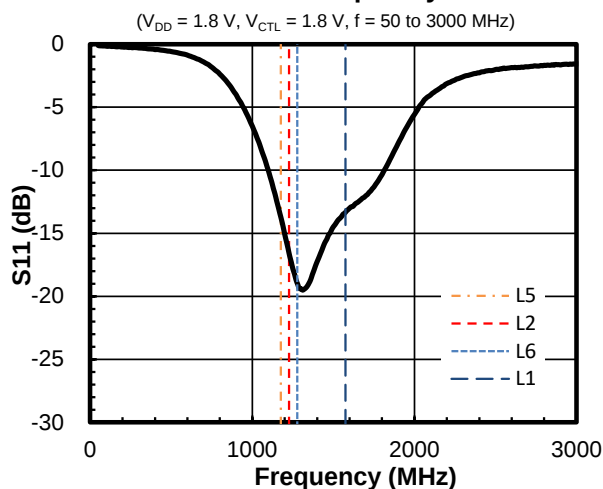
Out-of-band IIP3



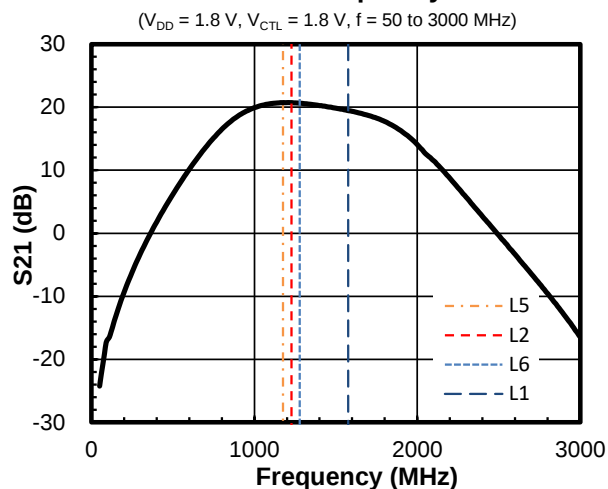
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

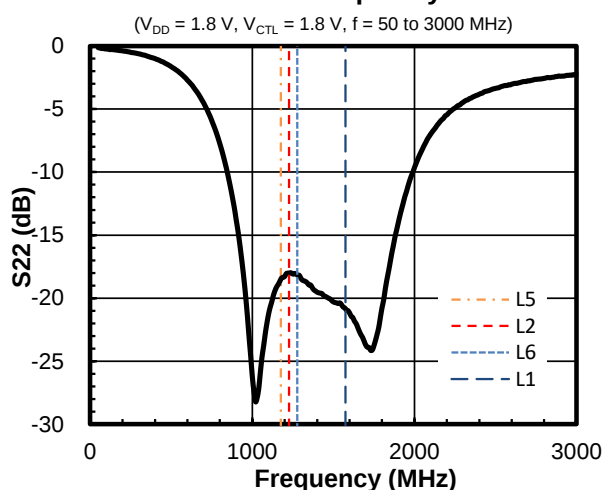
S11 vs. Frequency



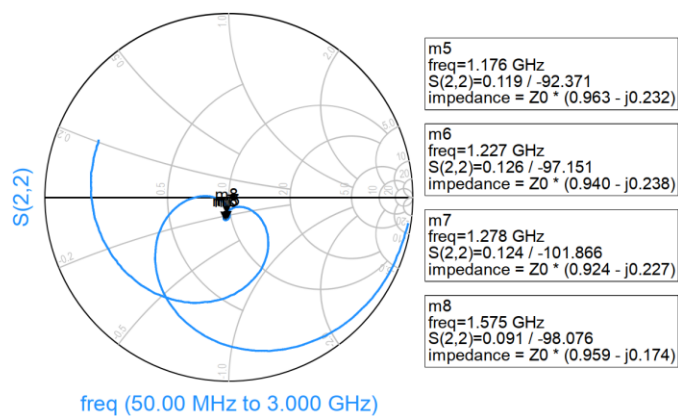
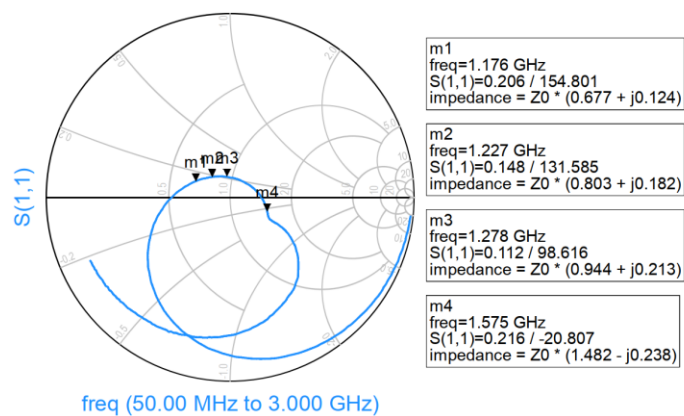
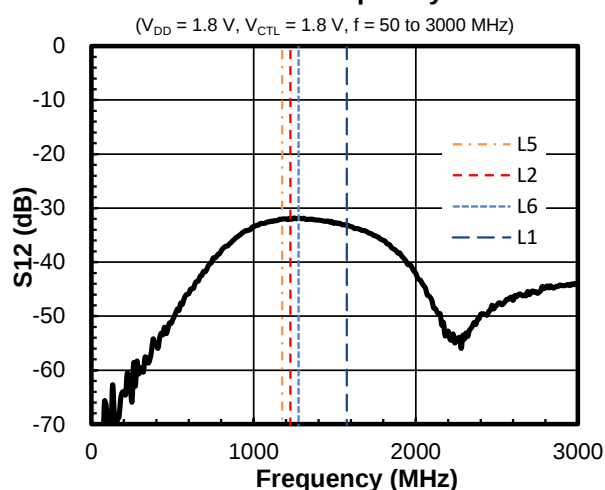
S21 vs. Frequency



S22 vs. Frequency



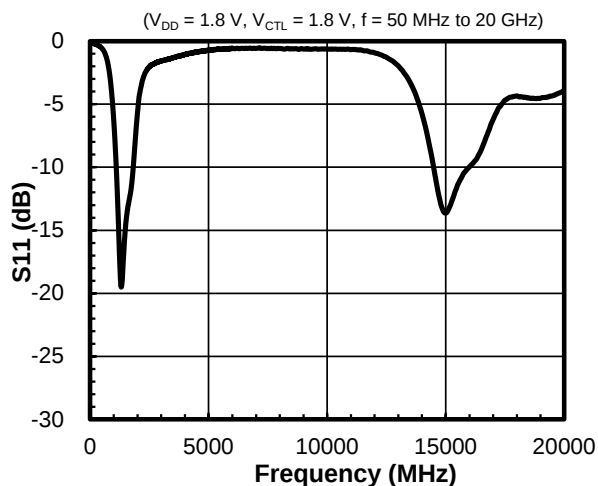
S12 vs. Frequency



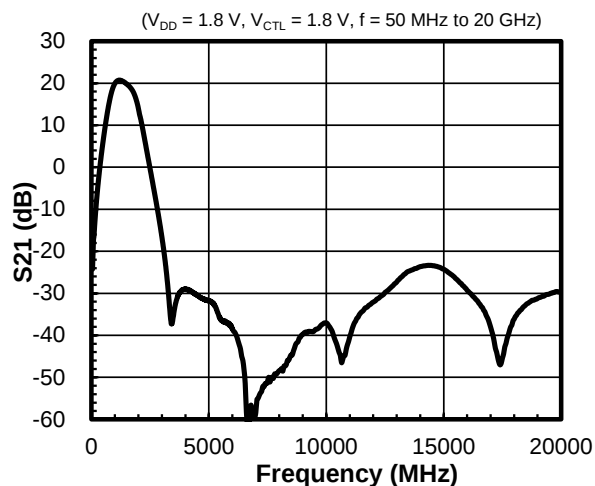
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

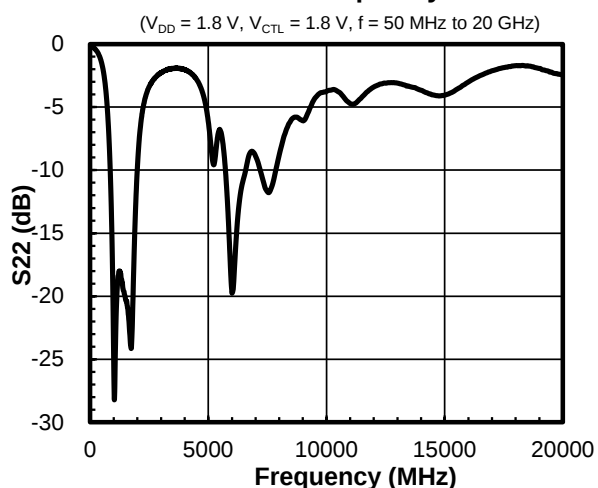
S11 vs. Frequency



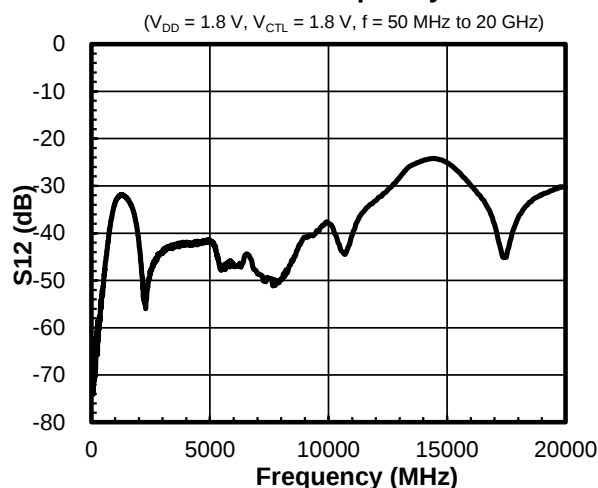
S21 vs. Frequency



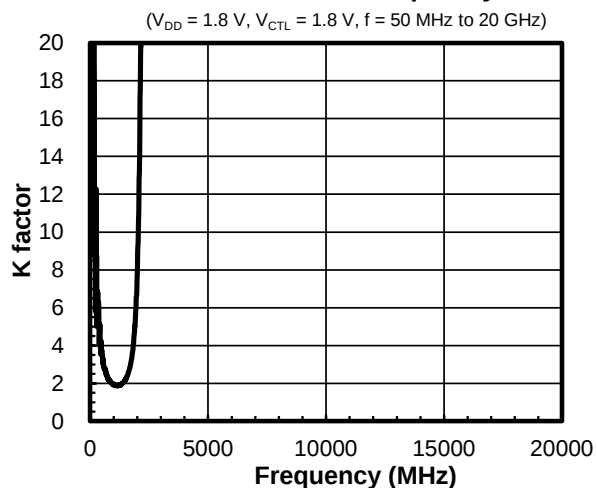
S22 vs. Frequency



S12 vs. Frequency



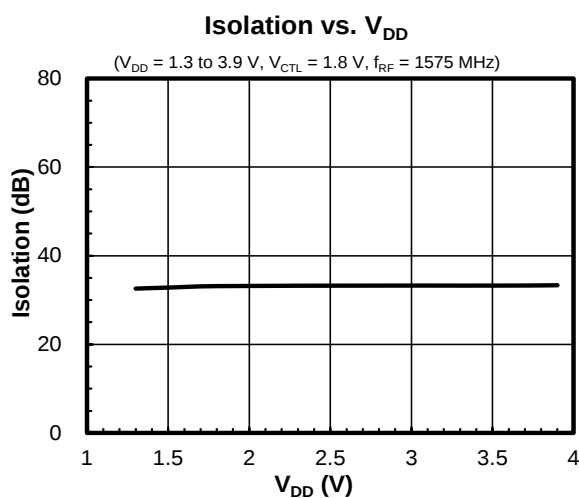
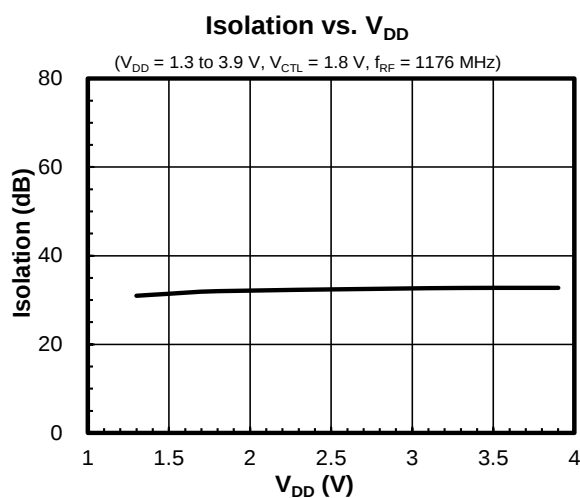
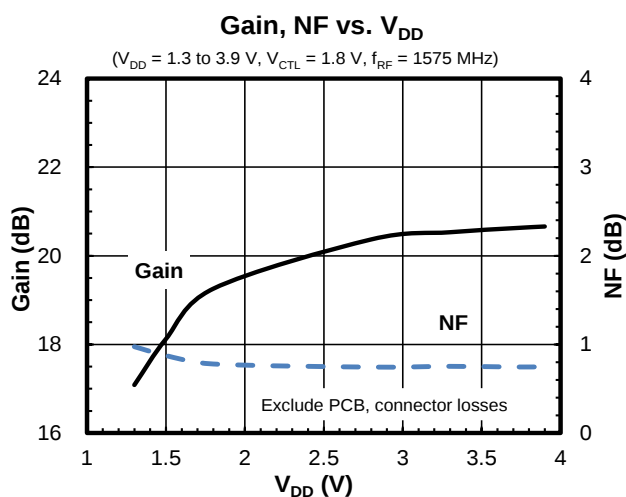
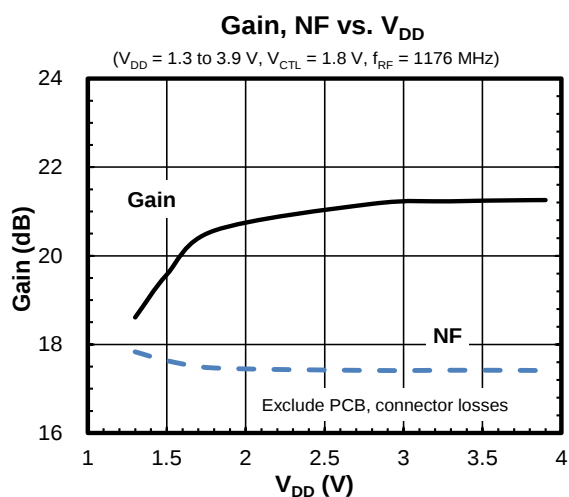
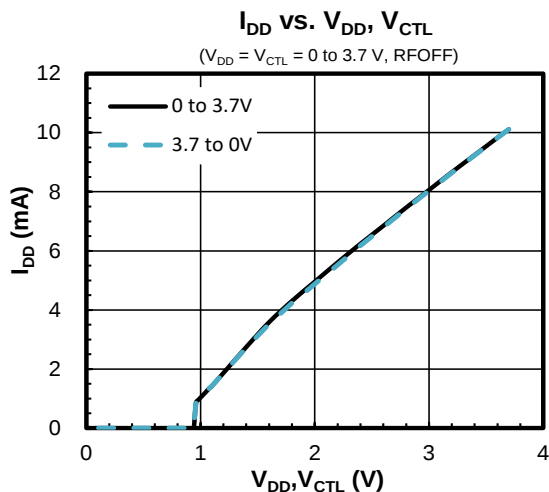
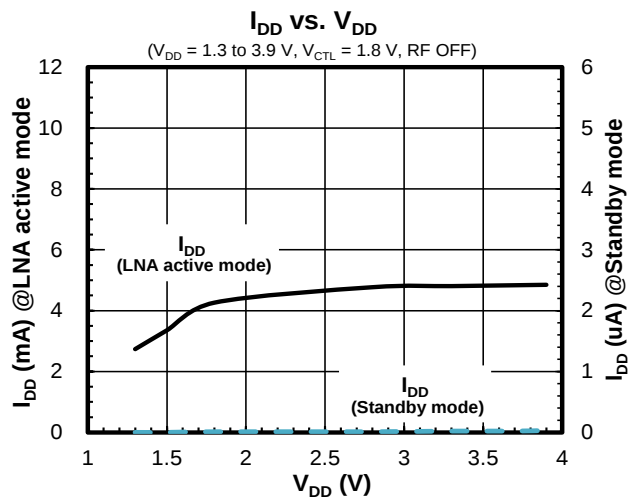
K factor vs. Frequency



■ TYPICAL CHARACTERISTICS

General conditions: $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit

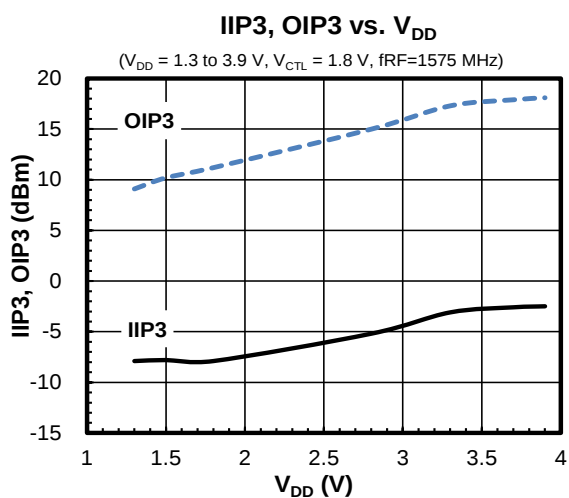
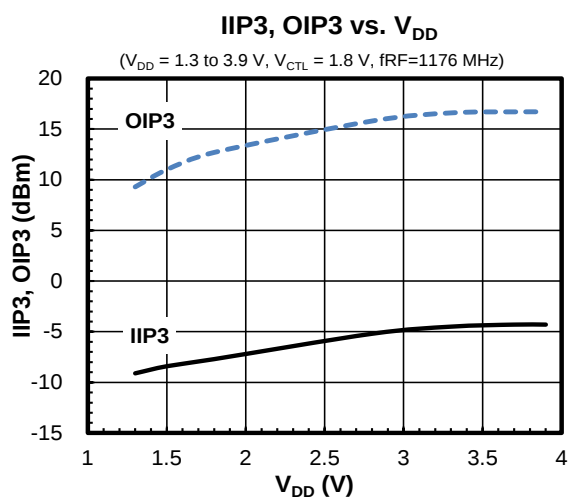
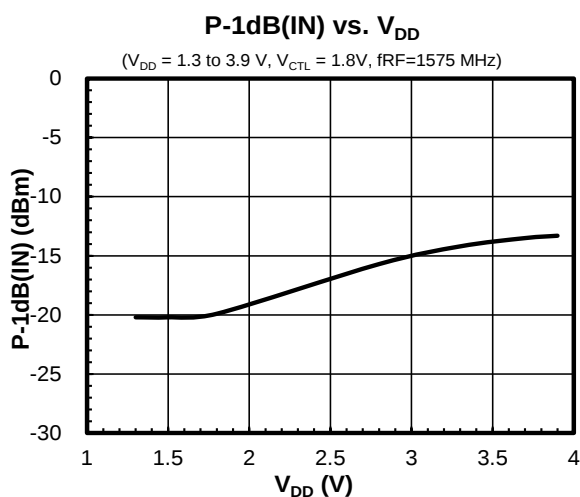
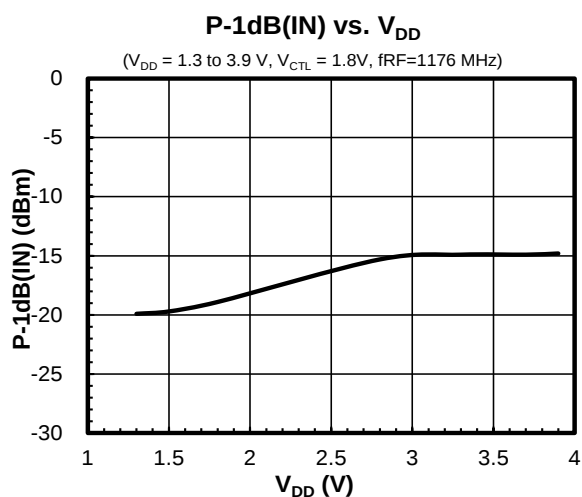
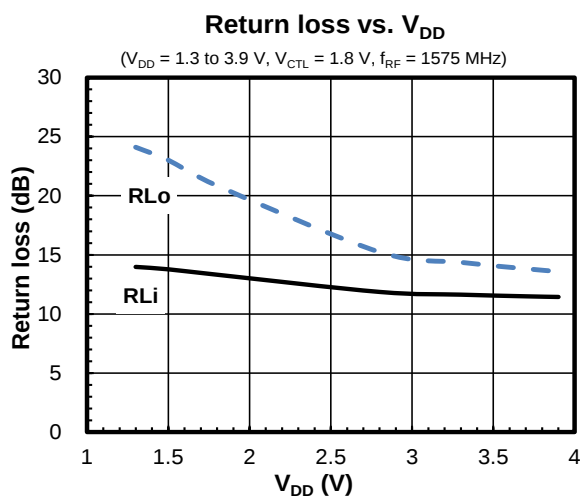
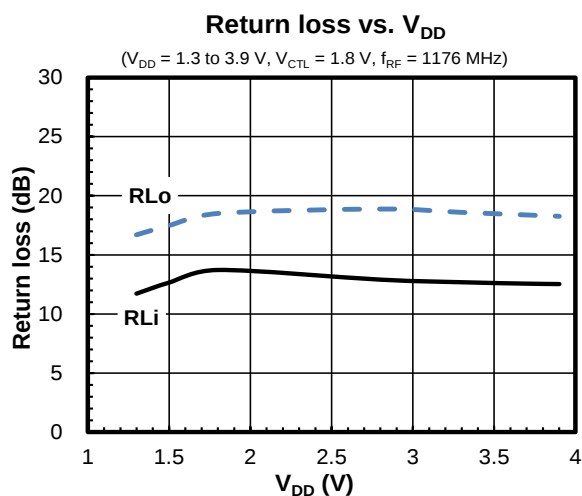
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)



■ TYPICAL CHARACTERISTICS

General conditions: $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit

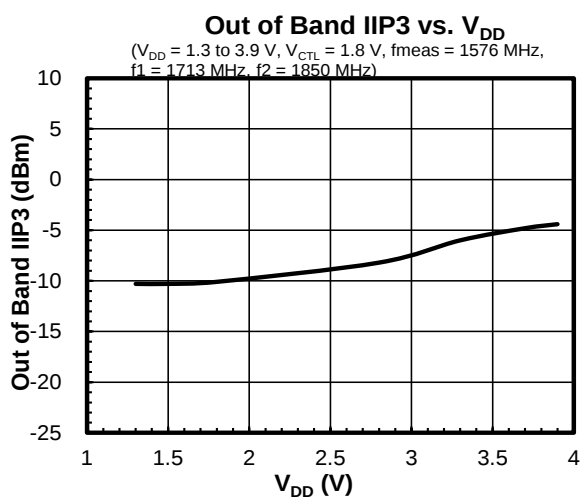
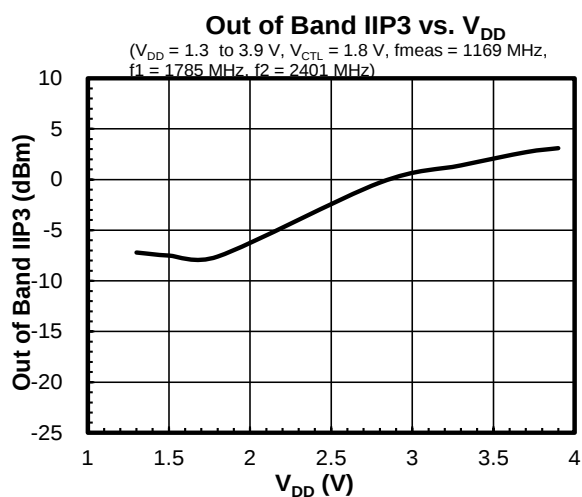
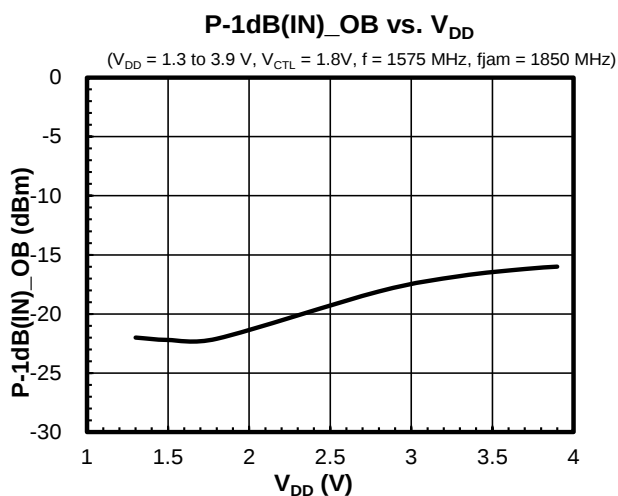
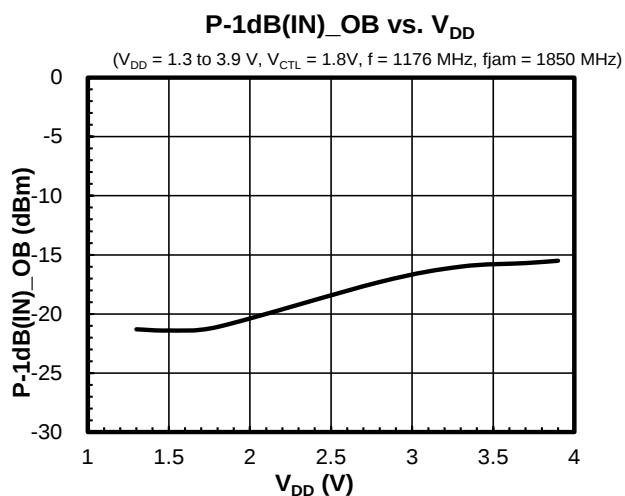
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)



■ TYPICAL CHARACTERISTICS

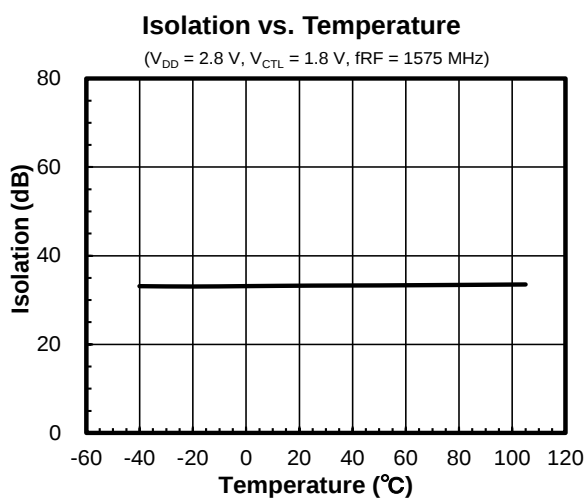
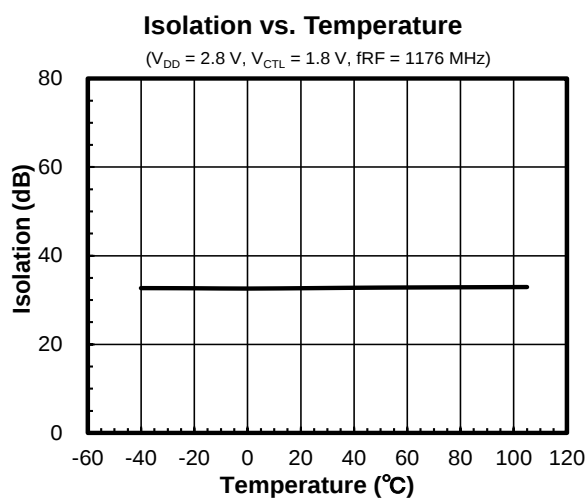
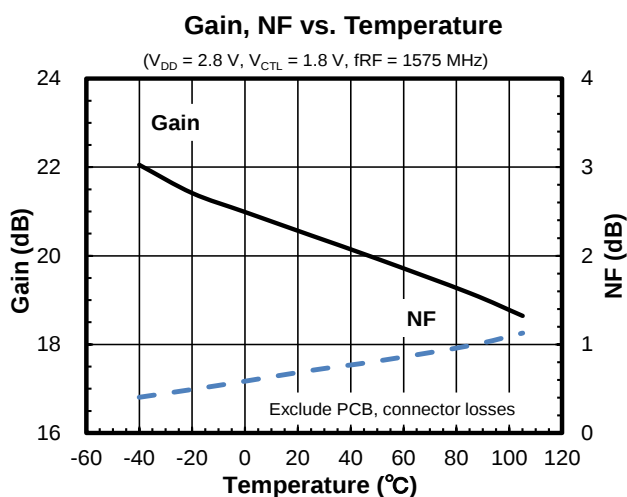
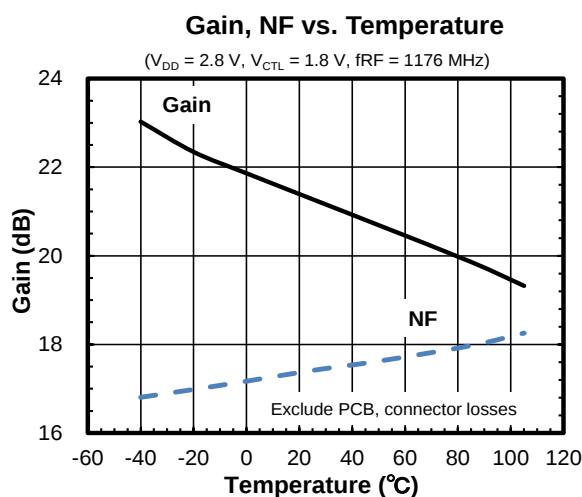
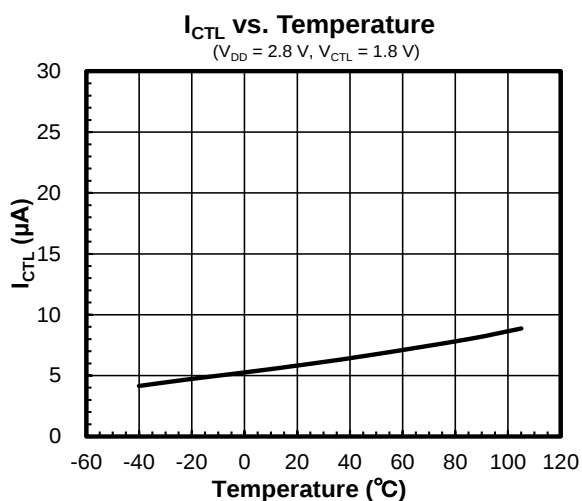
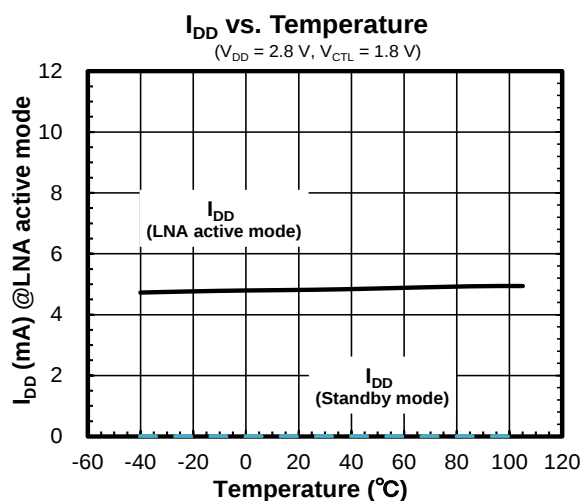
General conditions: $T_a = +25^\circ\text{C}$, $Z_s = Z_l = 50\Omega$, with application circuit

(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)



■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

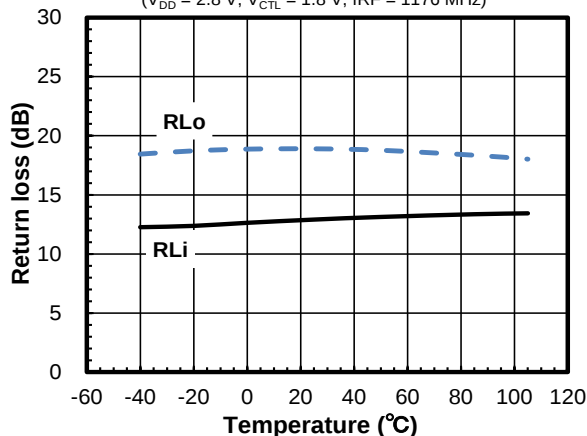


■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

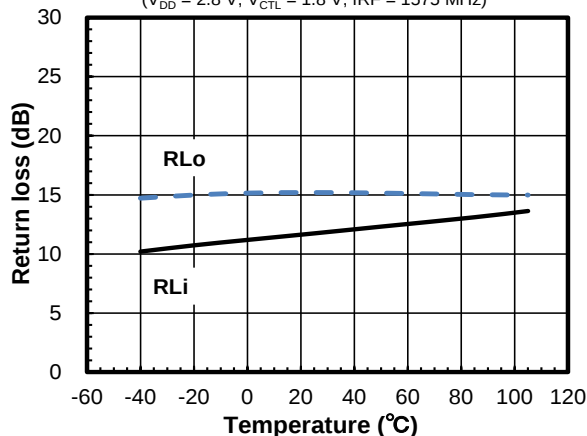
Return loss vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1176\text{ MHz}$)



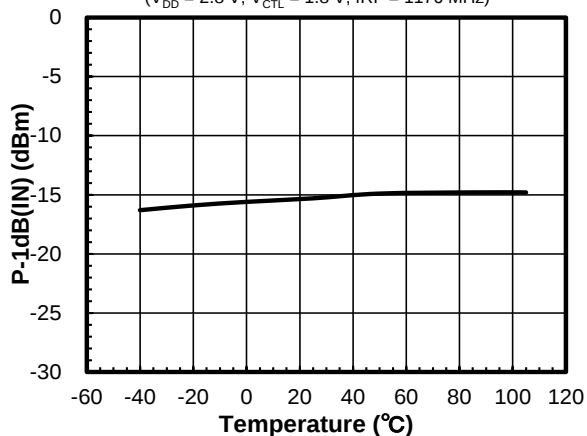
Return loss vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1575\text{ MHz}$)



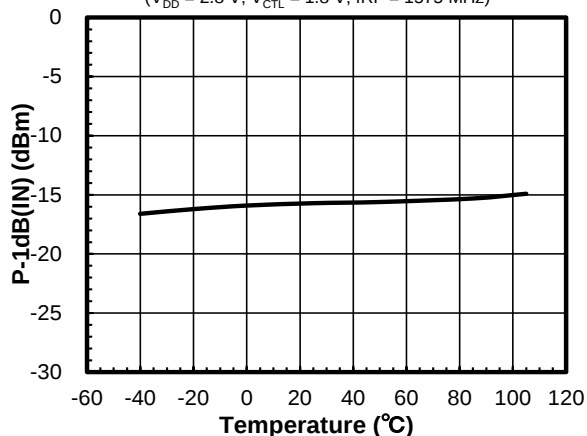
P-1dB(IN) vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1176\text{ MHz}$)



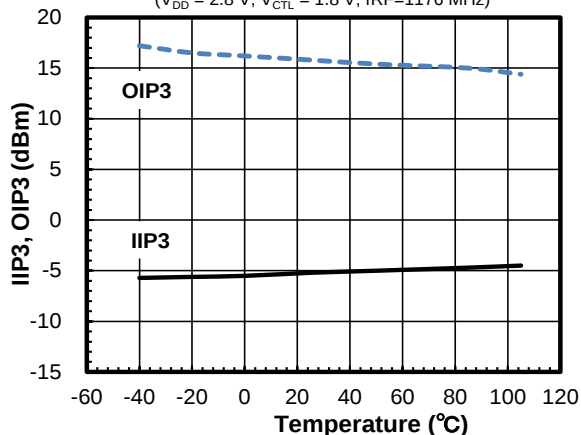
P-1dB(IN) vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1575\text{ MHz}$)



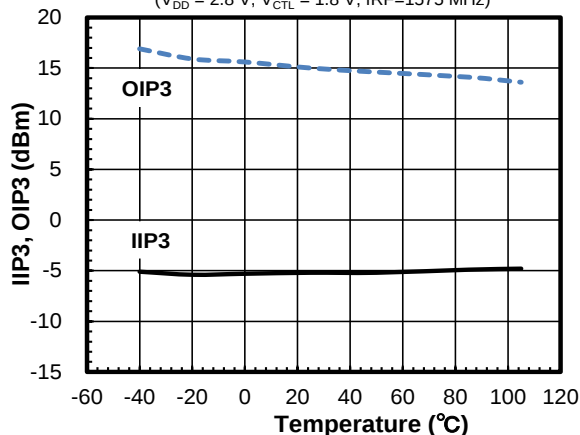
IIP3, OIP3 vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1176\text{ MHz}$)



IIP3, OIP3 vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{RF} = 1575\text{ MHz}$)

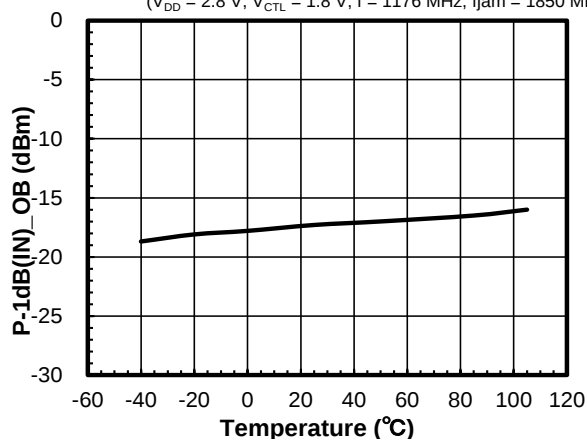


■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

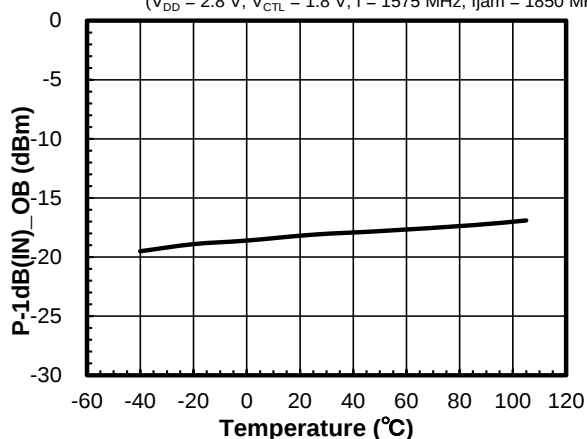
P-1dB(IN)_OB vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1176\text{ MHz}$, $f_{jam} = 1850\text{ MHz}$)



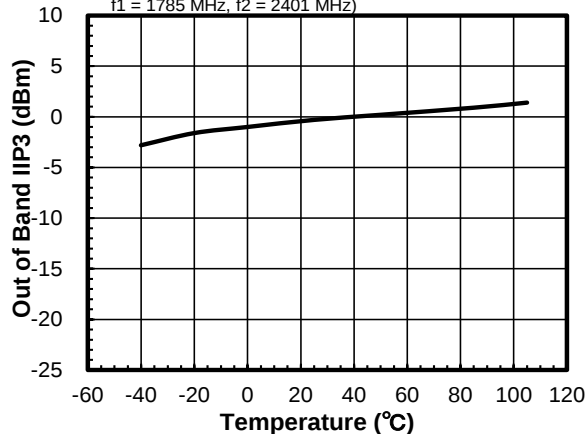
P-1dB(IN)_OB vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1575\text{ MHz}$, $f_{jam} = 1850\text{ MHz}$)



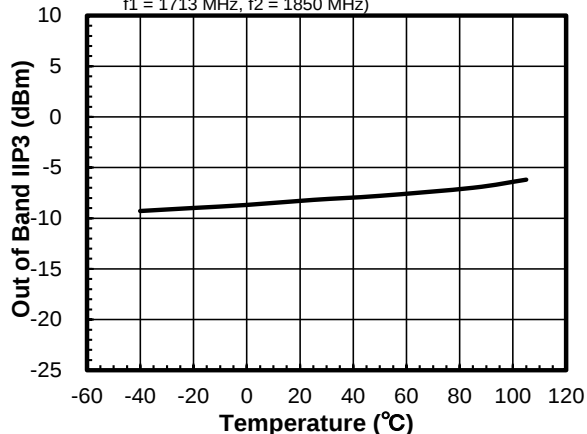
Out of Band IIP3 vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{meas} = 1169\text{ MHz}$,
 $f_1 = 1785\text{ MHz}$, $f_2 = 2401\text{ MHz}$)



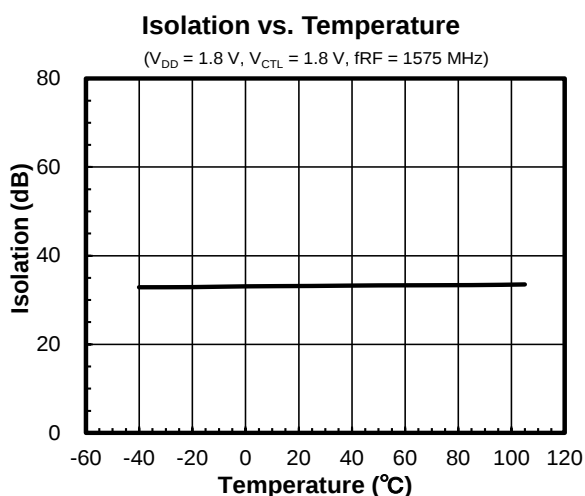
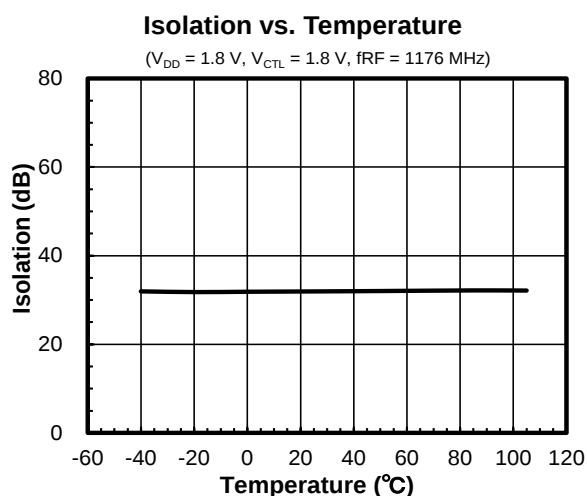
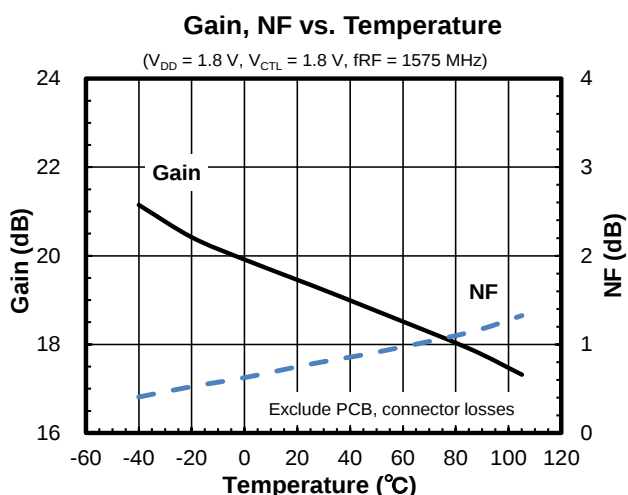
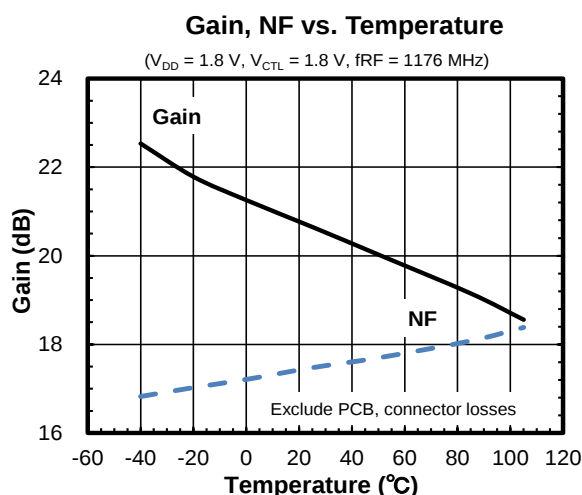
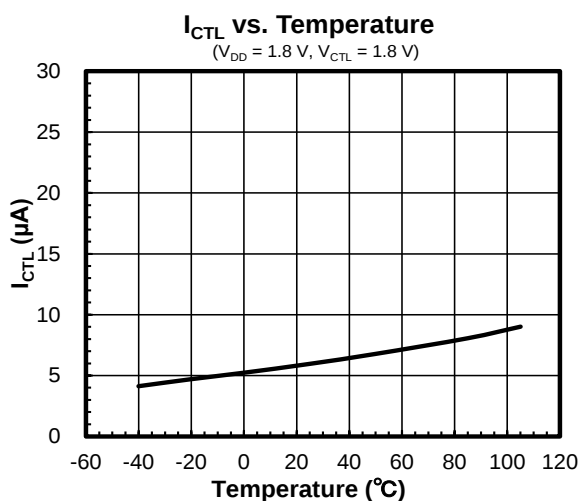
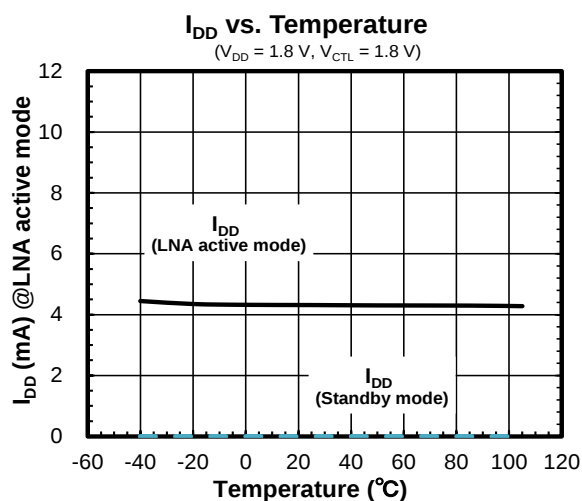
Out of Band IIP3 vs. Temperature

($V_{DD} = 2.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{meas} = 1576\text{ MHz}$,
 $f_1 = 1713\text{ MHz}$, $f_2 = 1850\text{ MHz}$)



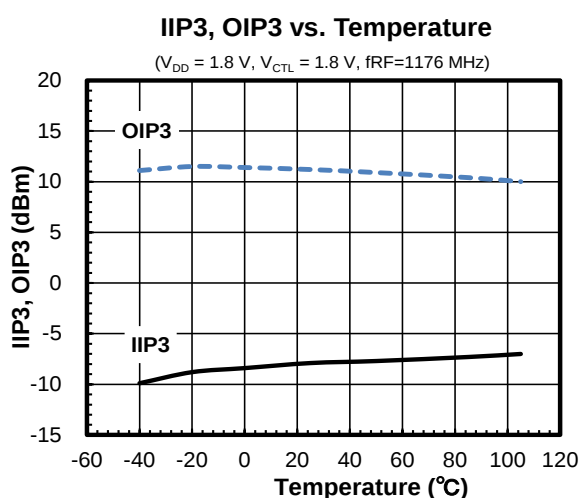
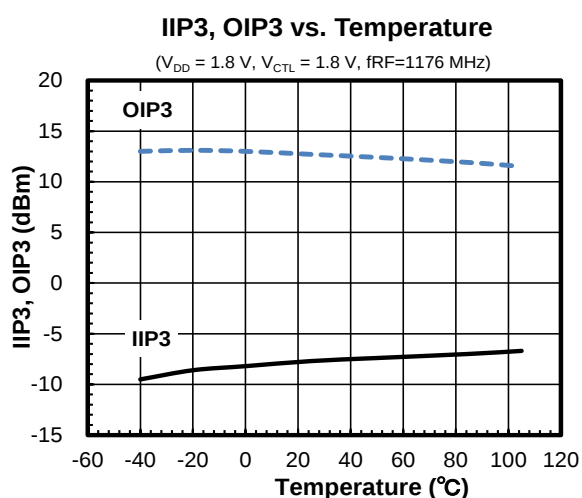
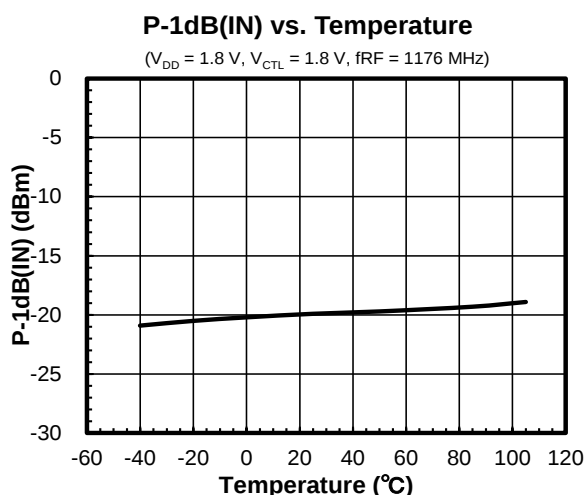
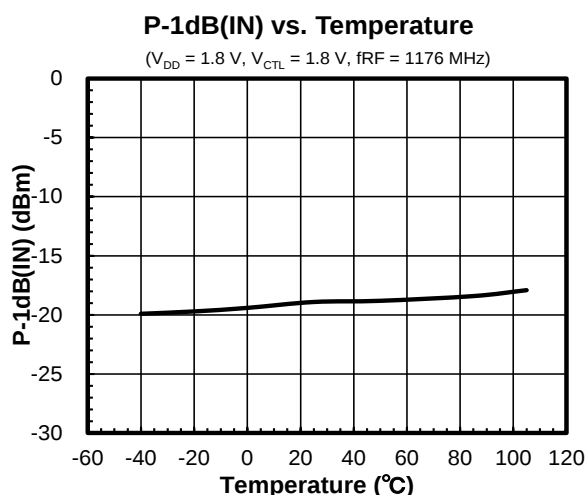
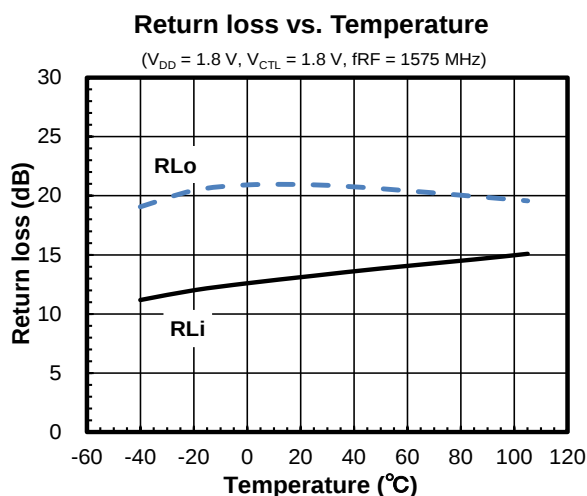
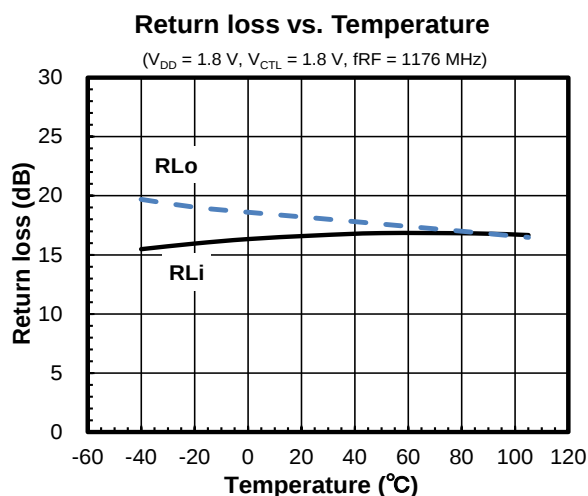
■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)



■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

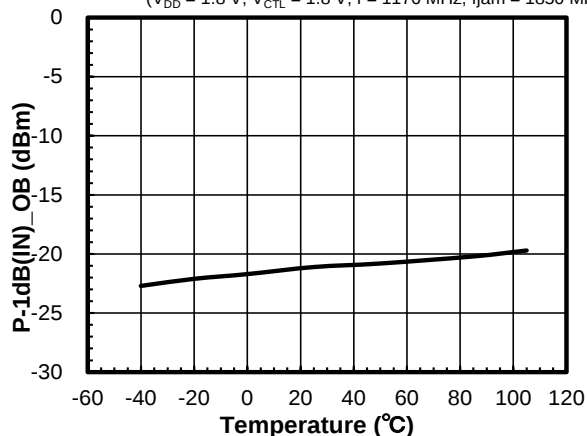


■ TYPICAL CHARACTERISTICS

General conditions: $V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $Z_s = Z_l = 50\Omega$, with application circuit
(Typical Characteristics are intended to be used as reference data; they are not guaranteed.)

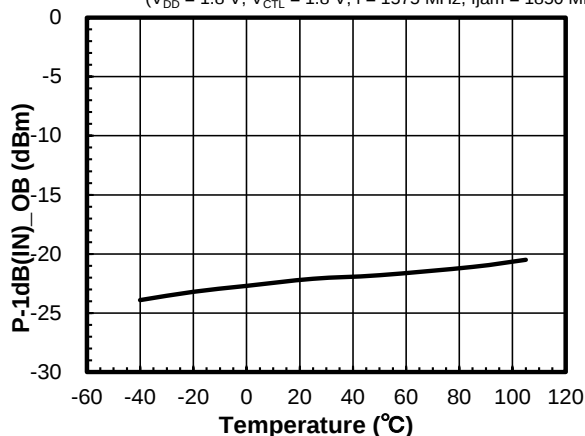
P-1dB(IN)_OB vs. Temperature

($V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1176\text{ MHz}$, $f_{jam} = 1850\text{ MHz}$)



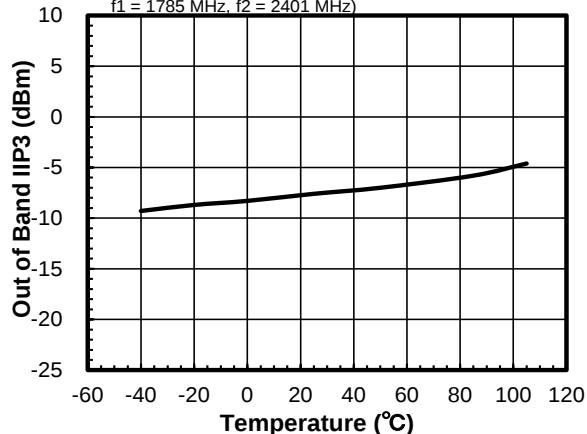
P-1dB(IN)_OB vs. Temperature

($V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f = 1575\text{ MHz}$, $f_{jam} = 1850\text{ MHz}$)



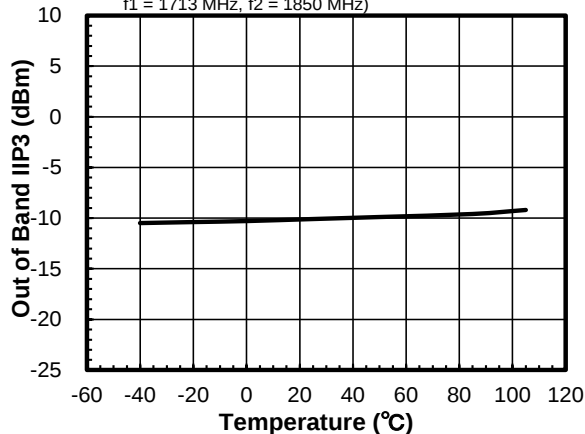
Out of Band IIP3 vs. Temperature

($V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{meas} = 1169\text{ MHz}$,
 $f_1 = 1785\text{ MHz}$, $f_2 = 2401\text{ MHz}$)

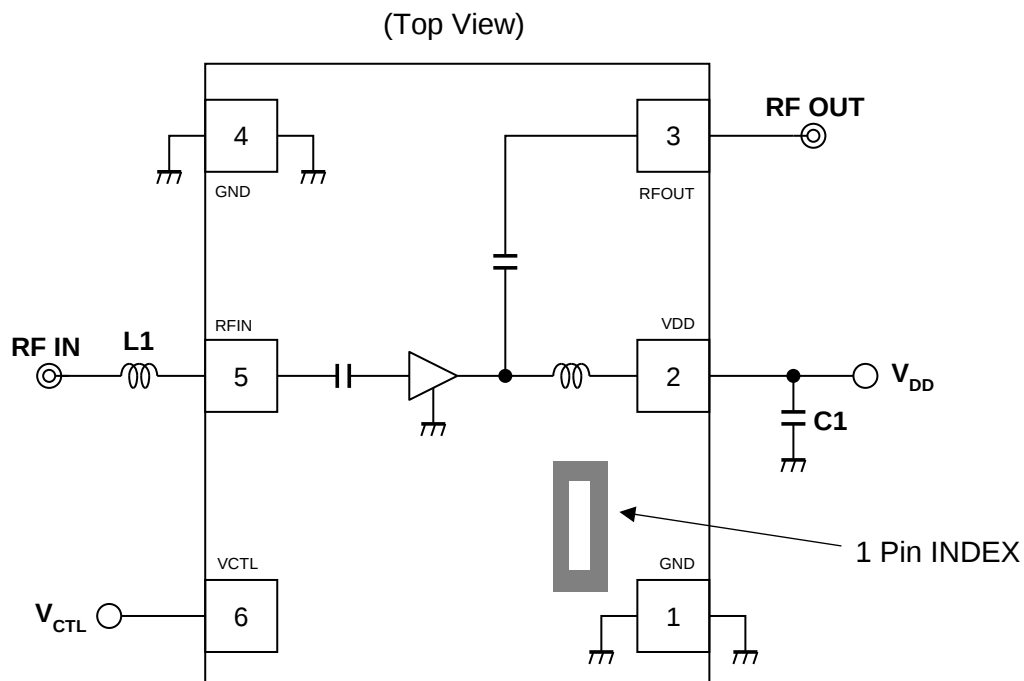


Out of Band IIP3 vs. Temperature

($V_{DD} = 1.8\text{ V}$, $V_{CTL} = 1.8\text{ V}$, $f_{meas} = 1576\text{ MHz}$,
 $f_1 = 1713\text{ MHz}$, $f_2 = 1850\text{ MHz}$)



■ APPLICATION CIRCUIT



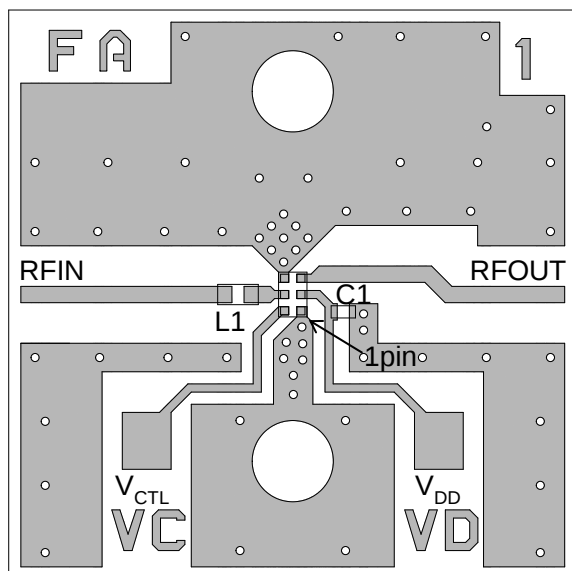
NT1193FAAE2S Typical Application Circuit

<Parts list>

Part ID	Value	Notes
L1	9.1 nH	LQW15AN series (MURATA)
C1	1000 pF	GRM03 series (MURATA)

● Evaluation Board / PCB layout

(Top View)



PCB

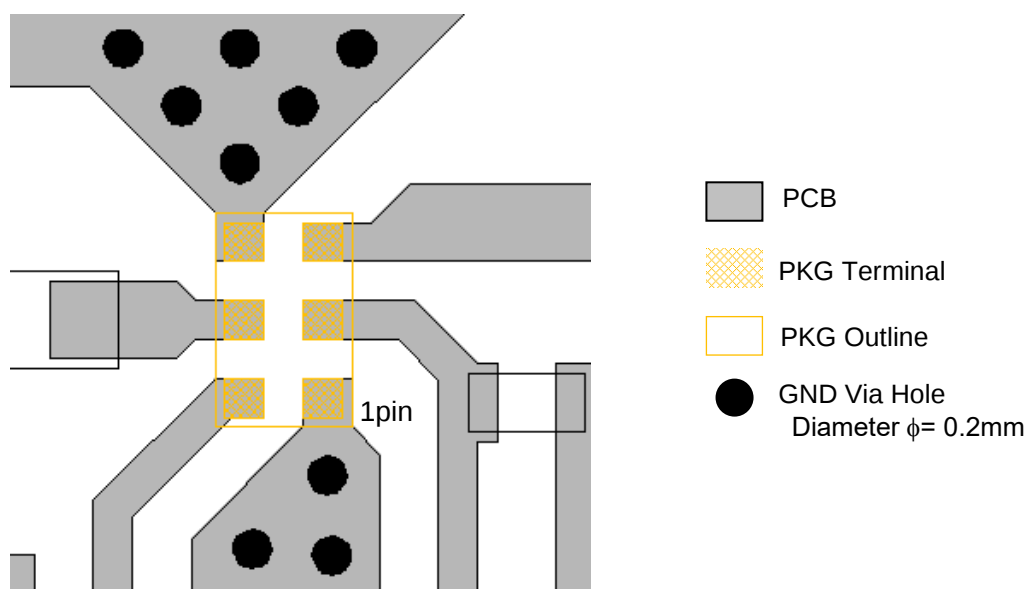
Substrate: FR-4

Thickness: 0.2 mm

Microstrip line width: 0.4 mm ($Z_0=50\Omega$)

Size: 14.0 x 14.0 mm

● PCB layout guideline

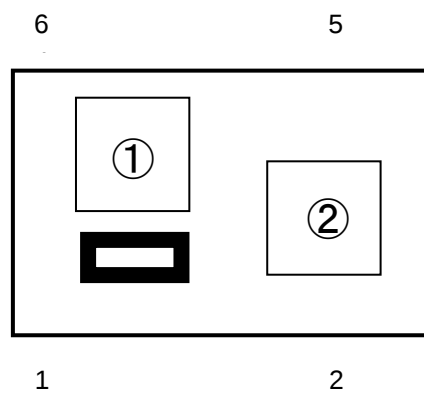


● PRECAUTIONS

- All external parts should be placed as close as possible to the LNA.
- For good RF performance, all GND terminals must be connected to PCB ground plane of substrate, and via-holes for GND should be placed near the LNA.

MARKING SPECIFICATION

- ① : Product Code
 ② : Lot Number ... Alphanumeric Serial Number



EPFFP-6-FA Marking Specification

NOTICE

There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or distributor before attempting to use AOI.

EPFFP-6-FA Marking List

Product Name	①
NT1193FAAE2S	9

■ APPLICATION NOTES

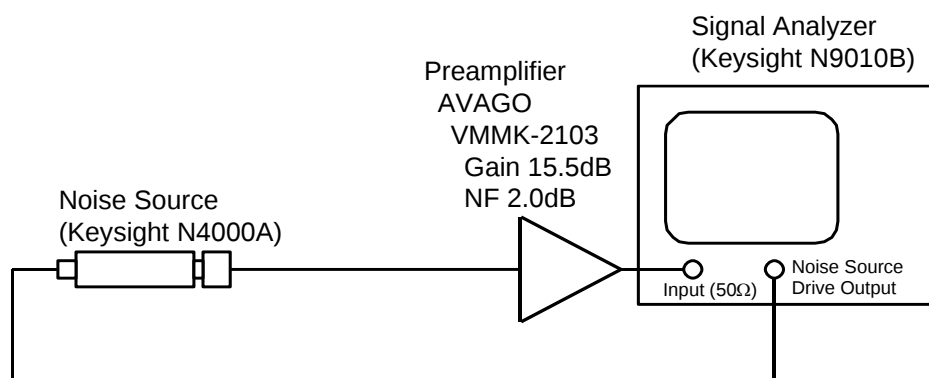
● NF Measurement Block Diagram

Measuring Instruments

Signal Analyzer : Keysight N9010B
Noise Source : Keysight N4000A

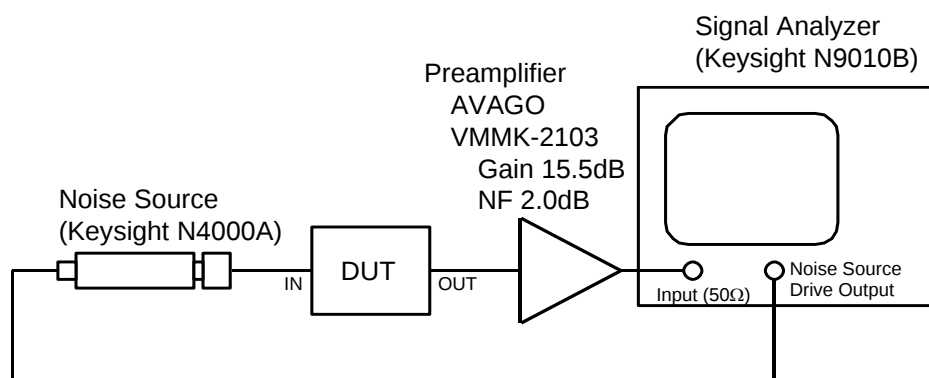
Setting the Signal analyzer

Mode/Measurement/View Selector
Mode : Noise Figure
Measurement : Noise Figure
Frequency
Center Frequency : 1.4 GHz
Span : 600 MHz
Points : 61
Amplitude
Attenuation : 0 dB
Signal Path : Internal Preamp on (Auto)
BW
Res BW : 4 MHz (Auto)
Meas Setup
Averaging : On
Avg/Hold Num : 16
Tcold : SNS Tcold On



*Preamplifier is used to improve NF measurement accuracy.
* Noise source, preamplifier and NF analyzer are connected directly.

Calibration Setup



* Noise source, DUT, preamplifier and NF analyzer are connected directly.

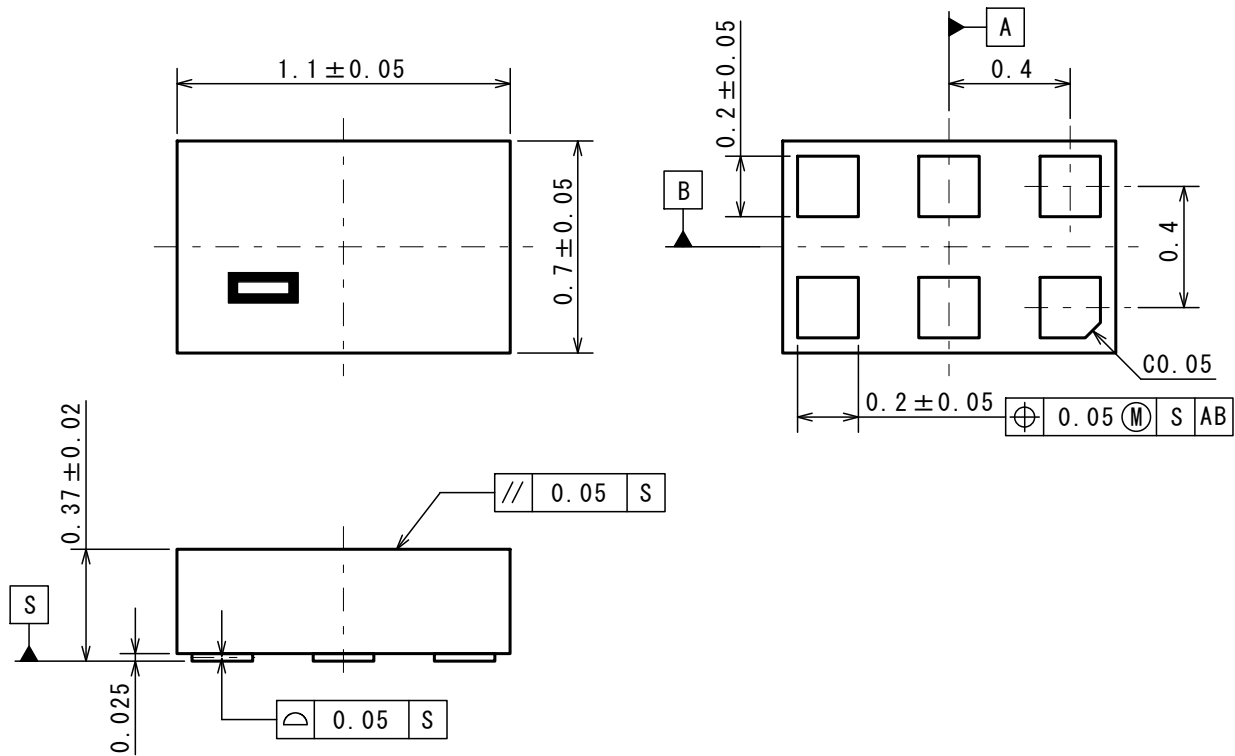
Measurement Setup

■ REVISION HISTORY

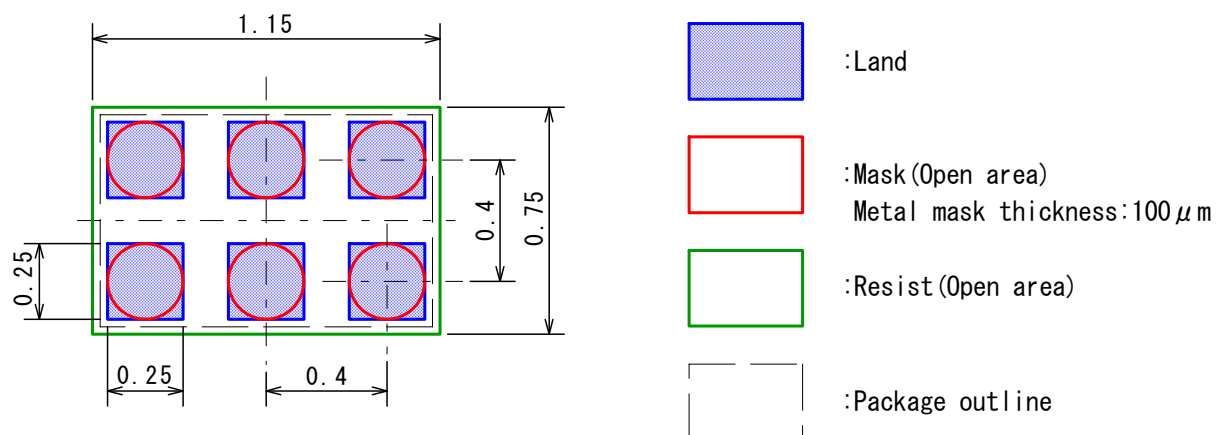
Date	Revision	Contents of Changes
March 13, 2024	Ver. 1.0	Initial release

■ PACKAGE DIMENSIONS

UNIT: mm



■ EXAMPLE OF SOLDER PADS DIMENSIONS



Nisshinbo Micro Devices Inc.

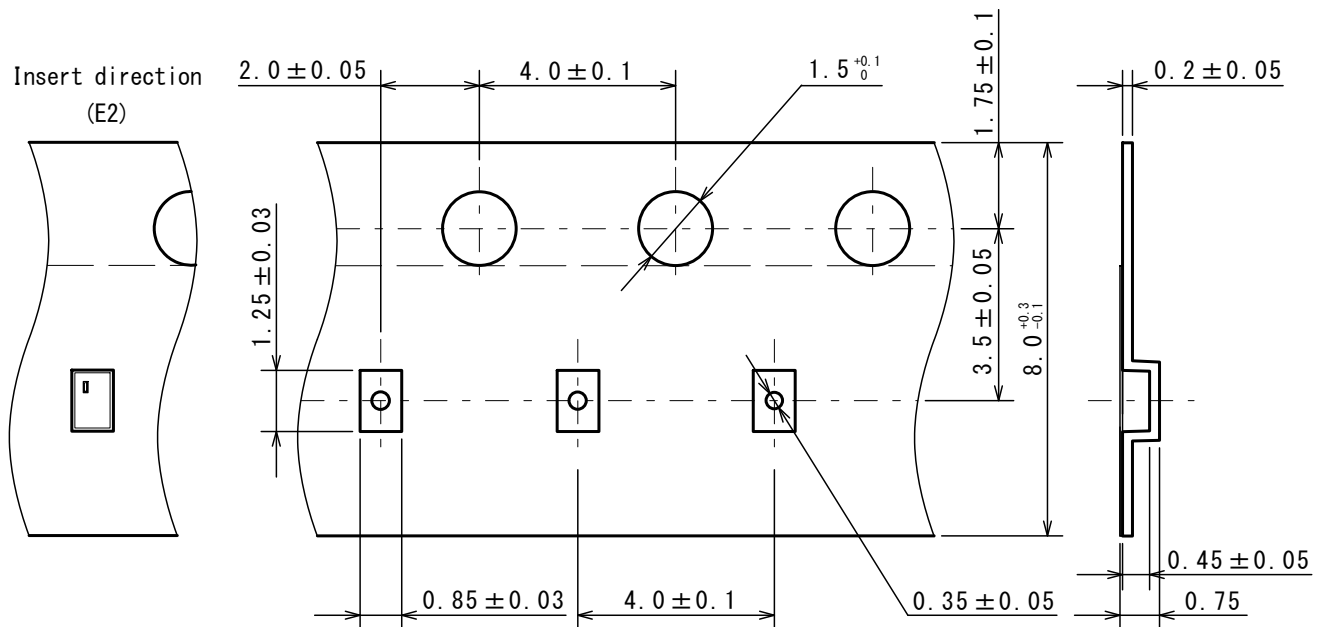
EPFFP-6-FA

PI-EPFFP-6-FA-E-A

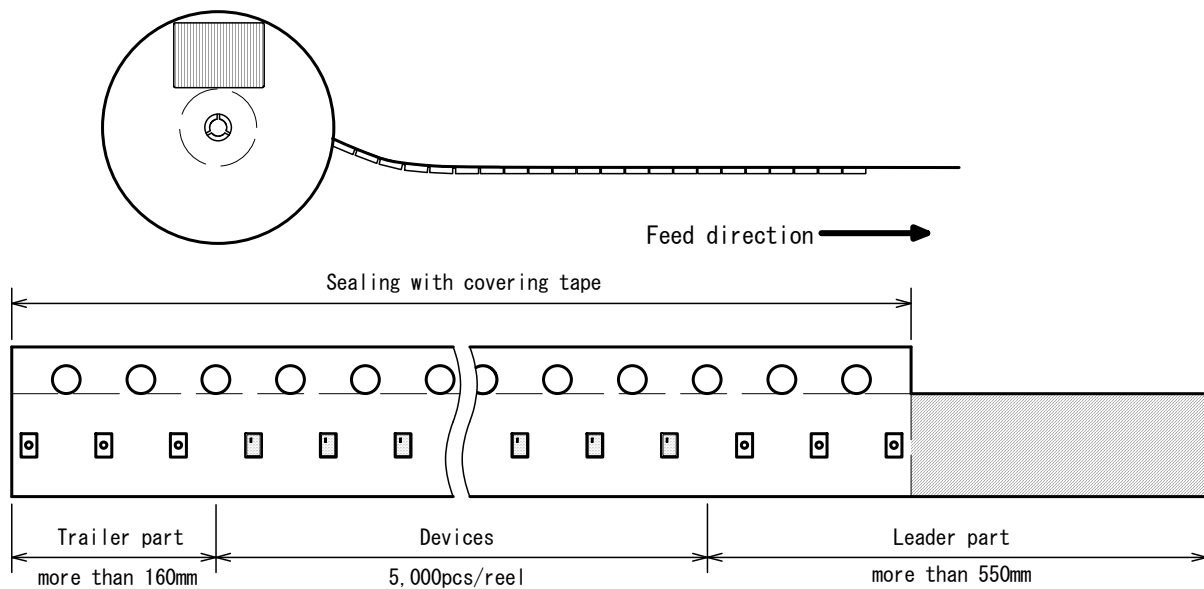
■ PACKING SPEC

UNIT: mm

(1) Taping dimensions / Insert direction



(2) Taping state

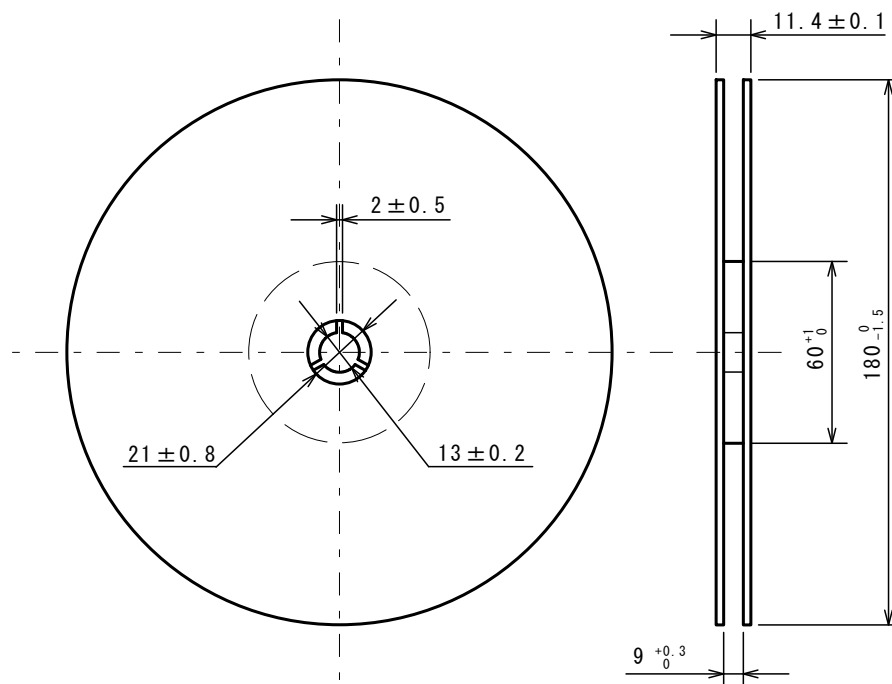


Nisshinbo Micro Devices Inc.

EPFFP-6-FA

PI-EPFFP-6-FA-E-A

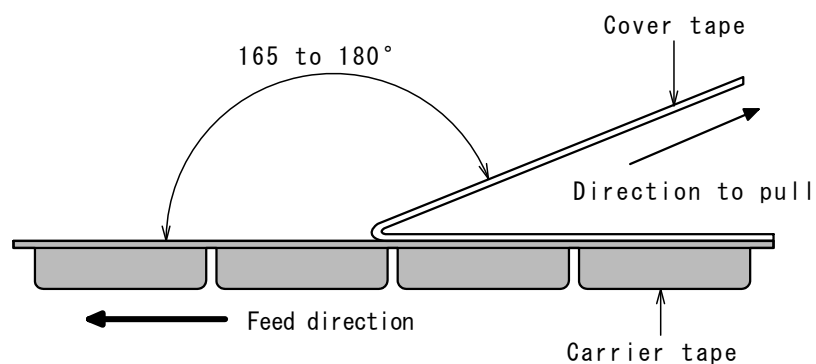
(3) Reel dimensions



(4) Peeling strength

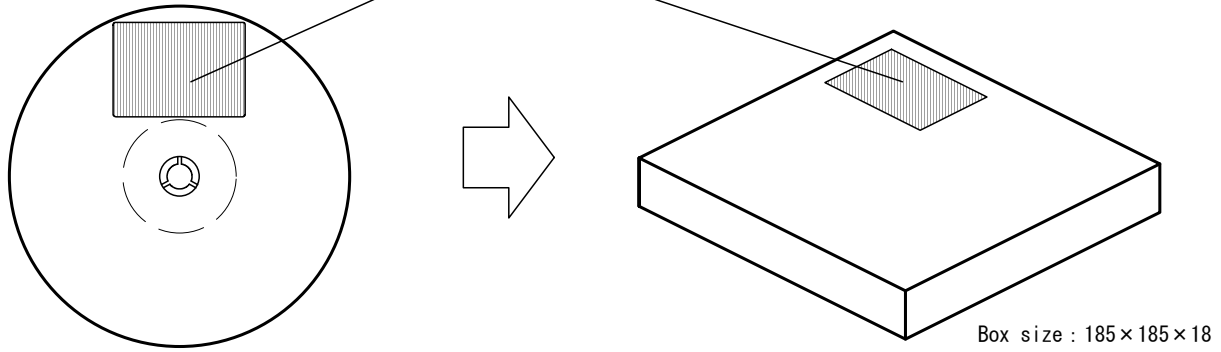
Peeling strength of cover tape

- Peeling angle 165 to 180° degrees to the taped surface.
- Peeling speed 300mm/min
- Peeling strength 0.1 to 1.0N

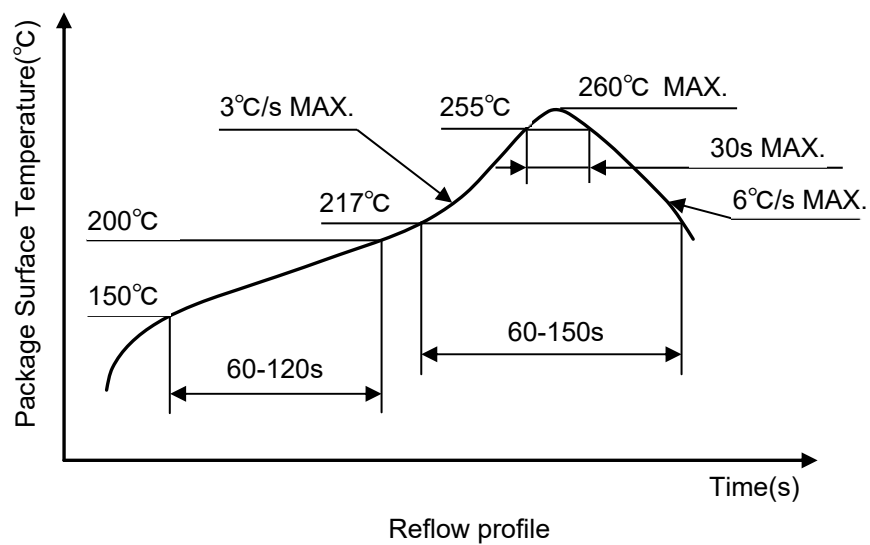


(5) Packing state

<Label> Product name, Quantity, Lot No., Mark



■ HEAT-RESISTANCE PROFILES



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[BGC100GN6E6327XTSA1](#) [BGA8U1BN6E6327XTSA1](#) [MGA-655T6-BLKG](#) [LTC6430AIUF-20#PBF](#) [HMC717ALP3E](#) [MMZ27333BT1](#)
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[MAAM-009286-TR3000](#) [MAAL-011111-TR0500](#) [GRF2105](#) [SKY66294-11](#) [GRF2133](#)